

# PCN

## AO-PCN-2022-036-A

# Introduction of 6" InGaAlP Thinfilm Chip for Multi Chip LED

02.01.2023

Dear Customer,

please review this **PCN** and provide your feedback in the **Customer approval form** (at the end of this PCN document) to your ams OSRAM sales partner before **06.02.2023** \*).

Your prompt reply will help ams OSRAM to assure a smooth and well executed transition. If ams OSRAM does not hear from your side by the due date, we will assume your (if you are a Distributor: and your customer's) full acceptance to this proposed change and its implementation.

ams OSRAM understands the time requirements your organization needs to approve this PCN. However, if you can provide ams OSRAM an estimated date your organization will have finalized this PCN review, ams OSRAM can use this date to plan continued production to secure your order needs during the transition time.

Your attention and response to this matter is highly appreciated.

**Please direct your inquiries to your local Sales office.**

- \*) ams OSRAM aligns with the widely recognized JEDEC/ECIA/IPC Joint Standard No. 46, which stipulates:
- Customers should acknowledge receipt of the PCN within 30 days of delivery of the PCN.
  - Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.
  - After acknowledgement, lack of additional response within the 90 day period constitutes acceptance of the change. If the customer requires additional time to perform sample testing, beyond the 90 day review period, an extension must be negotiated with the supplier.

**Subject of change:** Introduction of 6" InGaAlP Thinfilm Chip for Multi Chip LED

**Affected products:** LTRB RASF

**Reason for change:**

- Introduction of latest 6" chip technology to secure continuous supply
- Update of datasheet to latest format and correction of input, where needed.

Current status

New status

**Description of change:**

For details refer to document 2\_cip\_AO-PCN-2022-036-A

**Product identification:** Date code: 1423 (WWYY)

**Time schedule**

**for PCN material:**

(after implementation of change):

Final qualification report:

02.01.2023

Samples available:

02.01.2023

Intended Start of delivery:

02.04.2023<sup>\*)</sup>

<sup>\*)</sup> or earlier if released by customer and upon mutual agreement

**Time schedule**

**for Pre-PCN material:**

(prior to implementation of change):

Last time order date (LTO):

31.01.2024<sup>\*\*)</sup>

<sup>\*\*)</sup>  Lead time and LTO quantity shall be mutually agreed between OSRAM OS and customer.

Last time delivery date (LTD):

30.04.2024<sup>\*\*\*)</sup>

<sup>\*\*\*)</sup> planned last date for delivery of products of current status

**Assessment:**

No change of product reliability

**Documentation:**

Customer information package 2\_cip\_AO-PCN-2022-036-A;  
3\_cip\_AO-PCN-2022-036-A\_Rel

Note:

Pre-PCN material: Products of current status, means before implementation of the changes as described in the PCN.

PCN material: Products with implementation of the changes as described in the PCN.

## Customer approval form AO-PCN-2022-036-A

### Introduction of 6" InGaAlP Thinfilm Chip for Multi Chip LED

Please list product(s) affected in your application(s):

Please check the appropriate box below:

- |  |   |
|--|---|
| <input type="radio"/> <b>Approval:</b><br>We agree with the proposed change and accept start of the shipment upon availability of PCN material | <input type="radio"/> <b>Not relevant:</b><br>Change is not relevant for products in use. |
|--|---|

☐ **Change cannot be accepted:**

- ☐ **We have objections:**
- ☐ **We request following Information:**
- ☐ **We request following Samples:**
- ☐ **Expected approval date:**
- ☐ **Volume requirements for Pre-PCN material:**

☐ **Remarks:**

Sender:

Company:

Address / Location:

Signature:

Date:

Please return this approval form to your Sales partner.

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# PCN AO-PCN-2022-036-A Introduction of 6" InGaAlP Thinfilm Chip for Multi Chip LED

Customer information package

R&D-PD-LED-TLM and OS Q CQM ICI  
2023-01-02

## Agenda

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# AO-PCN-2022-036-A

## Introduction of 6” InGaAlP Thinfilm Chip for Multi Chip LED



### Reason for change

Item	Description
1.	Introduction of latest 6” chip technology to secure continuous supply
2.	Update of datasheet to latest format and correction of input, where needed.

## AO-PCN-2022-036-A

### Introduction of 6" InGaAlP Thinfilm Chip for Multi Chip LED

#### Description of change: new red chip

Item	Current status	New status
Picture (exemplary)		
Wafer size [mm]	100 (4")	150 (6")
Chip carrier substrate	Ge	Si
Chip size [ $\mu\text{m}$ ]	250 x 250	175 x 175
Height [ $\mu\text{m}$ ]	150	120



## AO-PCN-2022-036-A

### Introduction of 6" InGaAlP Thinfilm Chip for Multi Chip LED

#### Changes in the datasheets:

Page	Change Item	Reason for change	Old	New
1	Applications	New layout	Gaming, Amusement, Gambling Textile Illumination	Entertainment
2	Typ. $V_F$ at $I_F = 20\text{mA}$	Change of new chip	2.10V	2.15V

# AO-PCN-2022-036-A

## Introduction of 6” InGaAlP Thinfilm Chip for Multi Chip LED

Changes in the datasheets: Forward Voltage for Red.

Old						New					
<b>Characteristics</b> $I_F = 20\text{ mA}$ ; $T_S = 25\text{ °C}$						<b>Characteristics</b> $I_F = 20\text{ mA}$ ; $T_S = 25\text{ °C}$					
Parameter	Symbol		Values ● true green	Values ● red	Values ● blue	Parameter	Symbol		Values ● true green	Values ● red	Values ● blue
Forward Voltage <sup>2)</sup> $I_F = 20\text{ mA}$	$V_F$	min.	2.20 V	1.80 V	2.70 V	Forward Voltage <sup>2)</sup> $I_F = 20\text{ mA}$	$V_F$	min.	2.20 V	1.80 V	2.70 V
		typ.	2.65 V	2.10 V	2.90 V			typ.	2.65 V	2.15 V	2.90 V
		max.	3.10 V	2.40 V	3.30 V			max.	3.10 V	2.40 V	3.30 V

# AO-PCN-2022-036-A

## Introduction of 6" InGaAlP Thinfilm Chip for Multi Chip LED

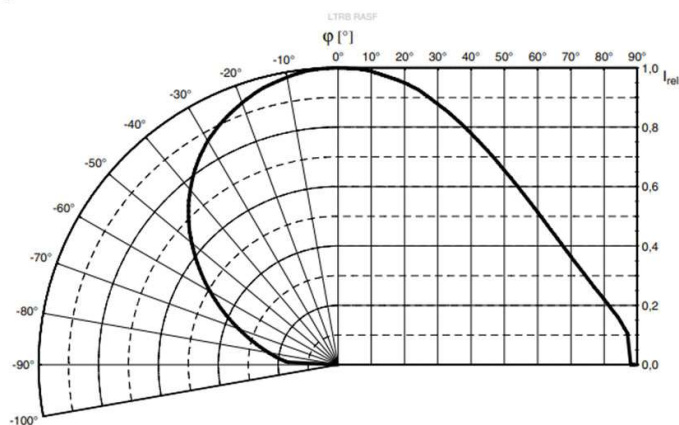
### Changes in the datasheets:

Old

New

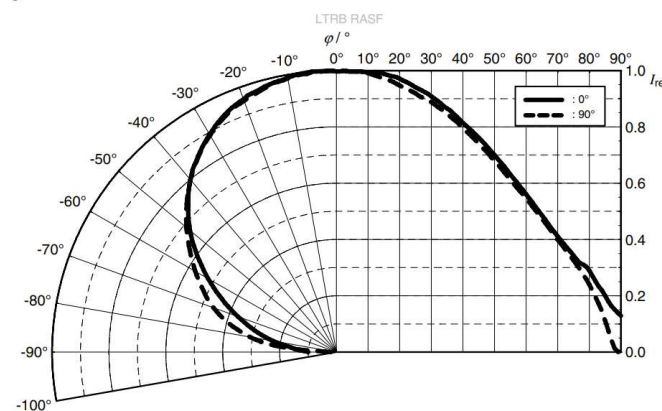
#### Radiation Characteristics <sup>6), 7)</sup>

$$I_{rel} = f(\phi); T_S = 25^\circ\text{C}$$



#### Radiation Characteristics <sup>6), 7)</sup>

$$I_{rel} = f(\phi); T_S = 25^\circ\text{C}$$



# AO-PCN-2022-036-A

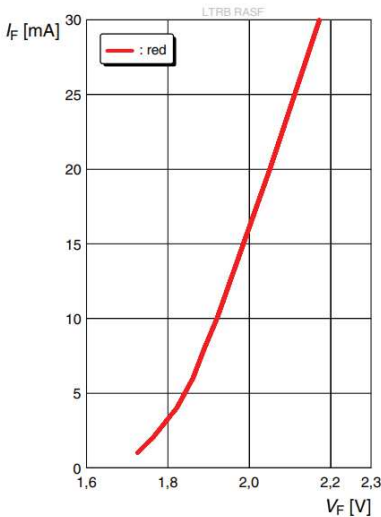
## Introduction of 6" InGaAlP Thinfilm Chip for Multi Chip LED

Changes in the datasheets: Forward Current - Red

Old	New
-----	-----

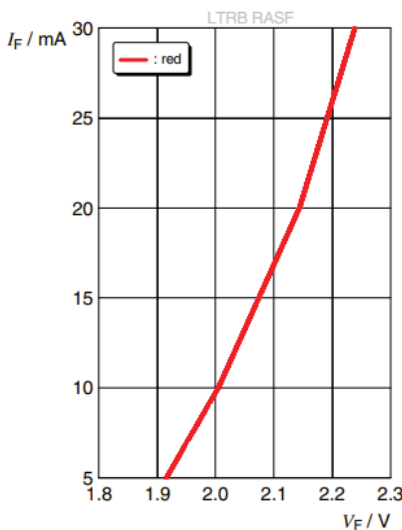
Forward current <sup>6)</sup>

$I_F = f(V_F); T_S = 25\text{ }^{\circ}\text{C}$



Forward current <sup>6)</sup>

$I_F = f(V_F); T_S = 25\text{ }^{\circ}\text{C}$



# AO-PCN-2022-036-A

## Introduction of 6" InGaAlP Thinfilm Chip for Multi Chip LED

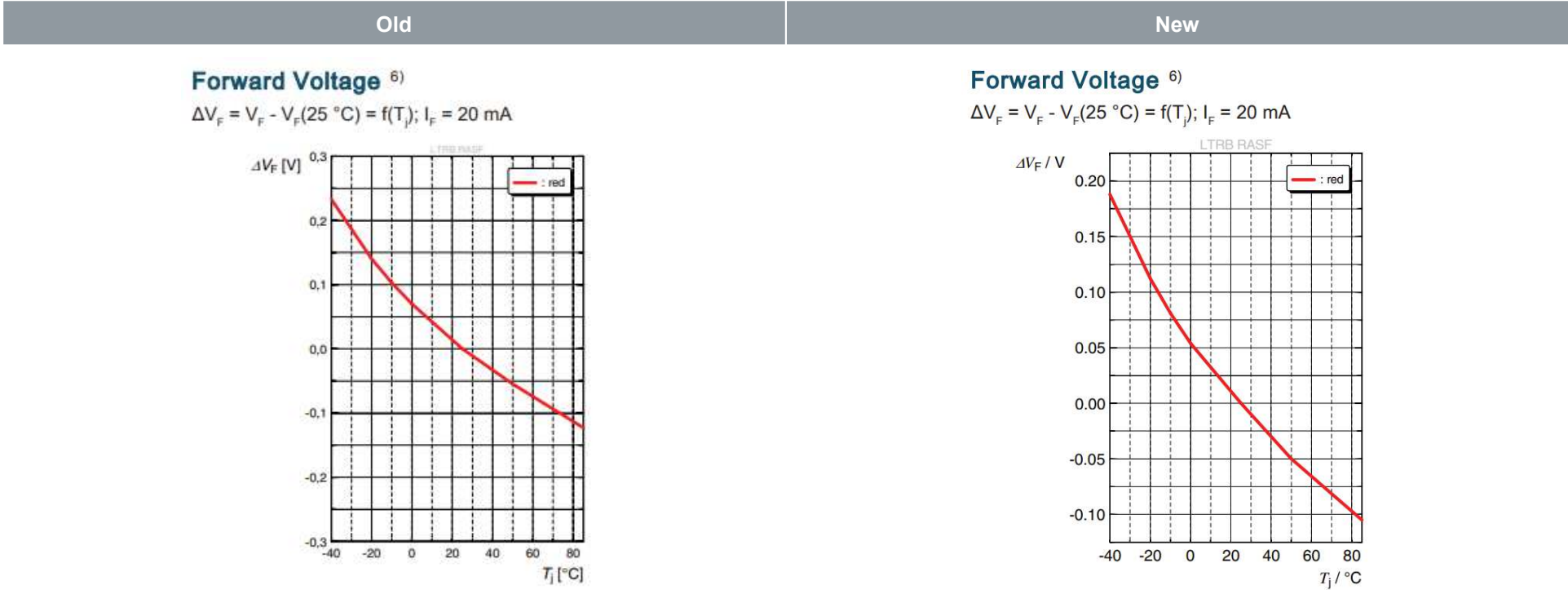
### Changes in the datasheets: Relative Luminous Intensity - Red



# AO-PCN-2022-036-A

## Introduction of 6" InGaAlP Thinfilm Chip for Multi Chip LED

Changes in the datasheets: Forward Voltage - Red

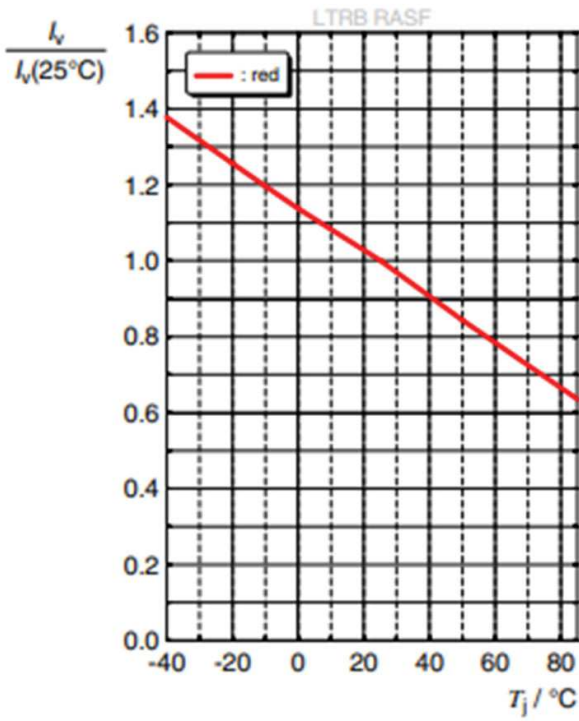
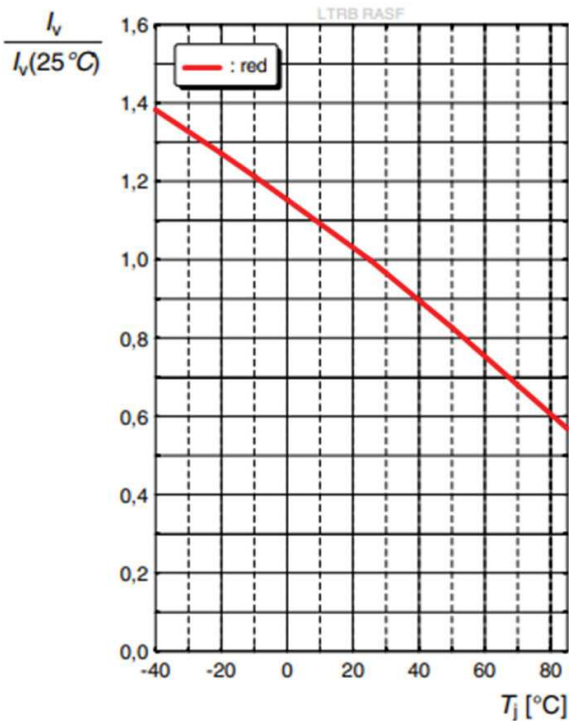


# AO-PCN-2022-036-A

## Introduction of 6" InGaAlP Thinfilm Chip for Multi Chip LED

Changes in the datasheets: Relative Luminous Intensity ( $T_j$ )

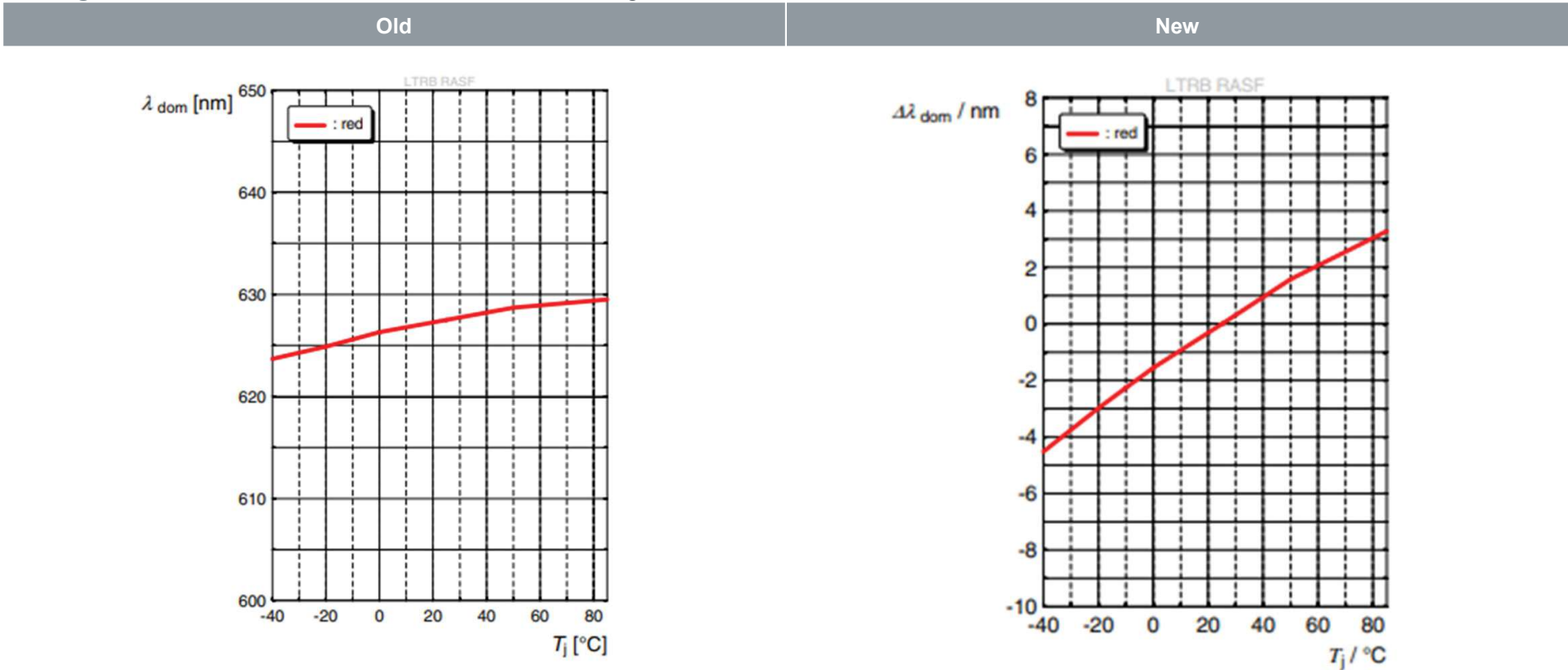
Old	New
-----	-----



# AO-PCN-2022-036-A

## Introduction of 6" InGaAlP Thinfilm Chip for Multi Chip LED

Changes in the datasheets: Dominant Wavelength





# AO-PCN-2022-036-A

## Introduction of 6" InGaAlP Thinfilm Chip for Multi Chip LED

### Changes in the datasheets: Updated Datasheet Version

Product type	Data sheet version <u>before PCN</u>	Data sheet version <u>after PCN</u>
LTRB RASF	1.6	1.7

Note: After PCN approval and shipment of new material, the new data sheet versions will be valid.  
Latest version of data sheet is accessible on the ams OSRAM homepage.

# AO-PCN-2022-036-A

## Introduction of 6” InGaAlP Thinfilm Chip for Multi Chip LED

### List of affected products

Brand	
Multi Chip LED	LTRB RASF

# AO-PCN-2022-036-A

## Introduction of 6” InGaAlP Thinfilm Chip for Multi Chip LED

### PCN Samples

Brand	
Multi Chip LED	LTRB RASF

Color code:  available

# AO-PCN-2022-036-A

## Introduction of 6" InGaAlP Thinfilm Chip for Multi Chip LED

### Time schedule

#### for PCN material (after implementation of change):

Final qualification report	02.01.2023	
Samples available	02.01.2023	
Intended Start of delivery	02.04.2023*)	*) or earlier if released by customer and upon mutual agreement

#### for Pre-PCN material (prior to implementation of change):

Last time order date (LTO)	31.01.2024 **)	** ) Lead time and LTO quantity shall be mutually agreed between OSRAM OS and customer.
Last time delivery date (LTD)	30.04.2024***)	*** ) planned last date for delivery of products of current status

Note:

Pre-PCN material: Products of current status, means before implementation of the changes as described in the PCN.

PCN material: Products with implementation of the changes as described in the PCN.

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# Qualification Report

# 220215C1

Subject	Qualification of LTRB RASF according to AO-PCN-2022-036-A
Date	02.01.2023
Tested device	LTRB RASF
Brand (including sub brands)	Multi Chip LED
Applies to	LTRB RASF

## Pre-conditioning according to Jedec Level II

Test Performed	Condition	Duration	Sample Size	Failures		
				El.	Opt.	Vis
Wet High Temperature Operating Life WHTOL <i>JESD22-A101</i>	$T_A = 40^{\circ}\text{C}$ ; r.H.= 93% $I_F = 5\text{mA}$	500h	4x30	0	0	0
Temperature Cycling TC <i>JESD22-A104</i>	$T_A = -40^{\circ}\text{C}/+85^{\circ}\text{C}$ 15min each extreme	300c	4x30	0	0	0
High Temperature Operating Life HTOL1 <i>JESD22-A108</i>	$T_A = 25^{\circ}\text{C}$ $I_F = 30\text{mA}$	500h	4x30	0	0	0
High Temperature Operating Life HTOL2 <i>JESD22-A108</i>	$T_A = 85^{\circ}\text{C}$ $I_F = 13\text{mA}$	500h	4x30	0	0	0
Pulsed Operating Life PLT <i>JESD22-A108</i>	$T_A = 25^{\circ}\text{C}$ $I_F = 100\text{mA}$ ; $t_p = 0.01\text{ms}$ ; DC = 3 %	1000h	4x30	0	0	0
Solderability (solder bath SMD) SD <i>IEC 60068-2-58</i>	$T_A = 245^{\circ}\text{C}$ $T_A = 260^{\circ}\text{C}$ method 1 (solder bath)	3s 10s	4x11	-	-	0
Sulphur dioxide test $\text{SO}_2$ <i>IEC 60068-2-42</i>	$T_A = 25^{\circ}\text{C}$ , r.H.= 75% $\text{SO}_2 = 25\pm 5\text{ppm}$	168h	4x30	0	0	0
Resistance to Solder Heat RSH <i>JESD22-A113</i>	Reflow soldering $260^{\circ}\text{C}$	3x	4x30	0	0	0
Electrostatic Discharge HBM ANSI/ESDA/JEDEC JS-001	Human Body Model	8000V	3x10	0	0	0

**Note: Lot A/B/C - Evaluation lot; Lot D - Control lot**

**Failure criteria:**

Electrical failures:	$U_f$ ( $I_f = 20\text{mA}$ )	blue chip	> 3,3 V; $\pm 10\%$ from initial value
		red chip	> 2,4 V; $\pm 10\%$ from initial value
		true green chip	> 3,10 V; $\pm 10\%$ from initial value
Optical failures:	$I_v$ ( $I_f = 20\text{mA}$ )	absolute limit: $\pm 50\%$ max.	
Visual failures:	acc JEDEC JESD22-B101		

**Conclusion: The tested devices representing the product family as stated in the applies to section fulfill the reliability requirements.**

## Disclaimer

PLEASE CAREFULLY READ THE BELOW TERMS AND CONDITIONS BEFORE USING THE INFORMATION.  
IF YOU DO NOT AGREE WITH ANY OF THESE TERMS AND CONDITIONS, DO NOT USE THE INFORMATION.

The Information contained in this Document does not constitute an independent warranty. The committed behavior is described in the Product data sheet and/or further, mutually agreed specifications.

Distribution of part or all of the contents of this Document to any 3rd party in any form without the prior permission of ams-OSRAM International GmbH is prohibited except in accordance with applicable mandatory law.

### Further explanations:

**Data:** The Data used in this Document consider the reliability test results under the mentioned driving conditions only. For Product information on the maximum operating conditions and the OSRAM standard qualification profile please refer to the Product data sheet or contact your local sales partner.

**Conditions:** The conditions for the generation of the Data are as follows:

1. The Data and curves shown in this Document are based on experiments carried out under laboratory conditions on a random sample size of LED/IRED/Laser/Detector with readouts at discrete readout times (where applicable). Thus, the Data above represent a limited number of production lots only and may differ between different assembly lots over time (including chip or package changes). Thus, the behavior of the LED/IRED/Laser/Detector in the final application may differ from the Data. The behavior of the LED/IRED/Laser/Detector at conditions or readout times deviating from those stated above may not be deduced from the Data.

2. If applicable:

a) Extended driving conditions:

The tested driving conditions exceed the maximum limits stated in the Product data sheet. Therefore, a reduced lifetime or an accelerated degradation is expected. Failure limits noted in the Document refer to the testing condition according to the OSRAM standard Product qualification profile and not to the actual testing condition.

b) Extended testing duration:

The testing duration exceed the OSRAM standard qualification profile of the mentioned Product. Failure limits noted in the Document refer to the testing duration according to the OSRAM standard Product qualification profile and not to the actual testing duration.

c) Exceeding standard qualification conditions – (Product data sheet limits not affected):

The tested driving conditions exceed the OSRAM standard qualification profile of the mentioned Product. Therefore a reduced lifetime or an accelerated degradation is expected. Failure limits noted in the Document refer to the testing condition according to the OSRAM standard Product qualification profile and not to the actual testing condition.

3. For long term operation additional failure modes of the chip or package can occur which are not shown in this Document.

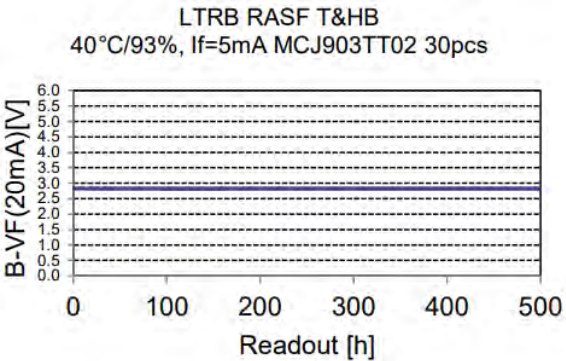
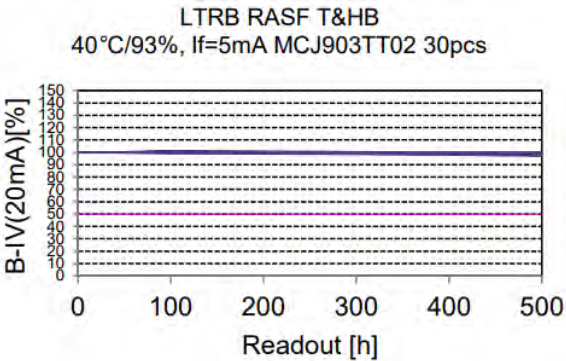
4. Possible differences in the thermal management of OSRAM and customer's setup may lead to a different aging behavior.



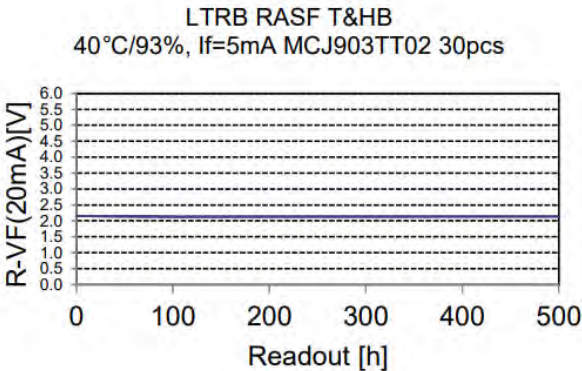
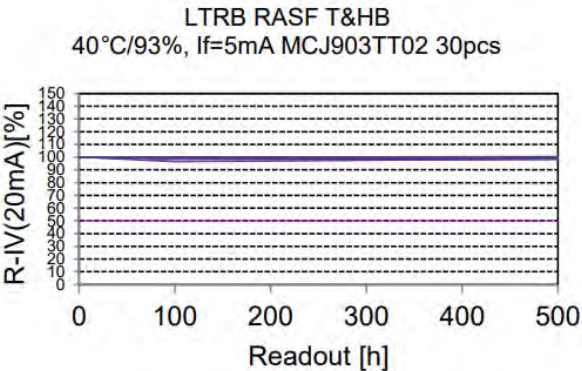
WHTOL 40°C/93%r.H; 5mA

Lot A - Eval

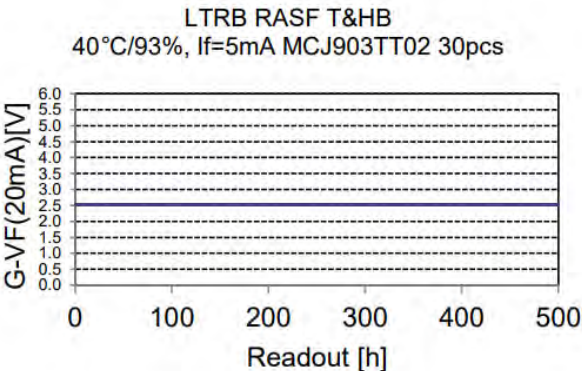
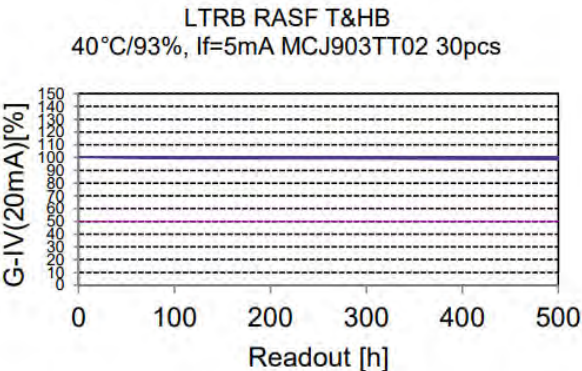
Blue chip



Red chip



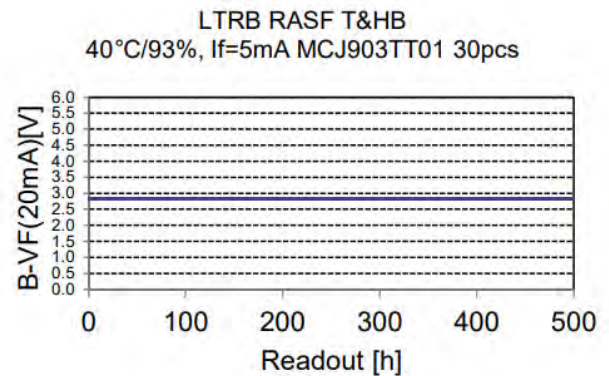
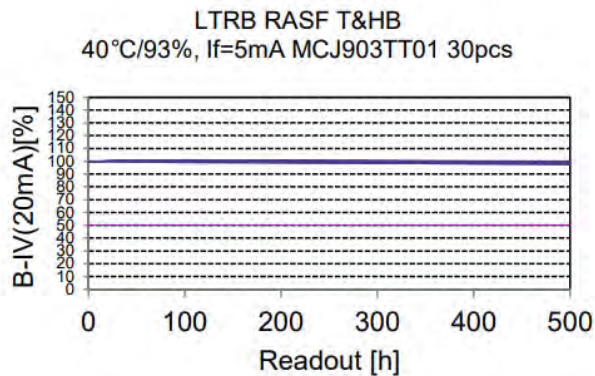
True green chip



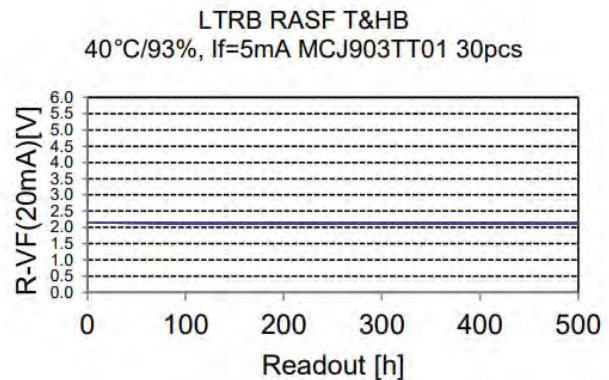
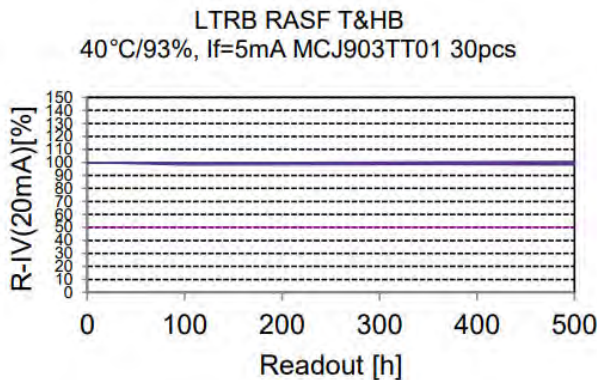
WHTOL 40°C/93%r.H; 5mA

Lot B - Eval

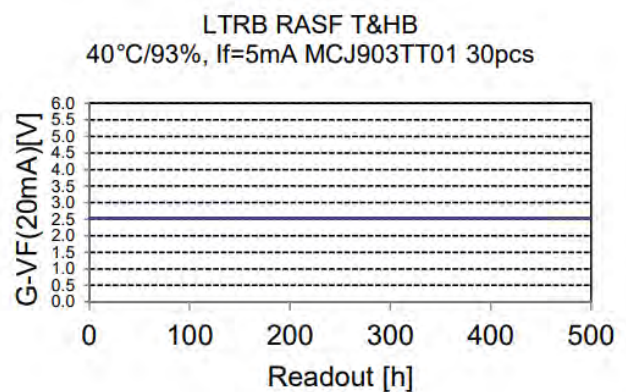
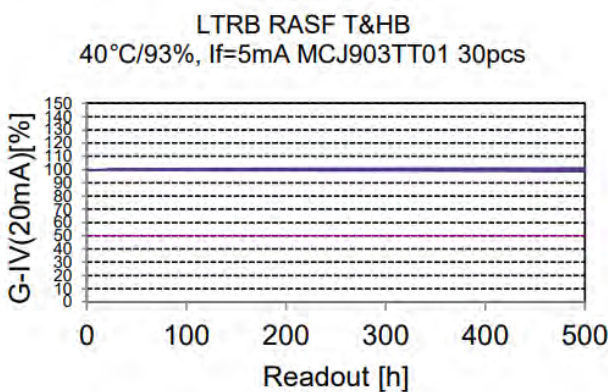
Blue chip



Red chip



True green chip

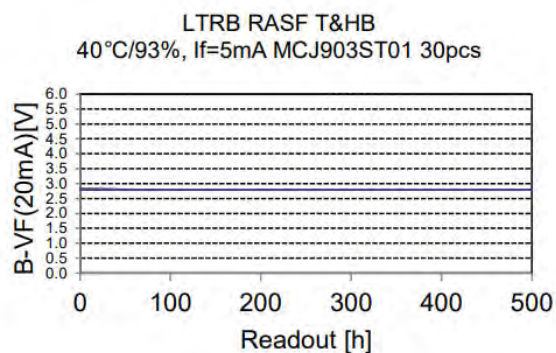
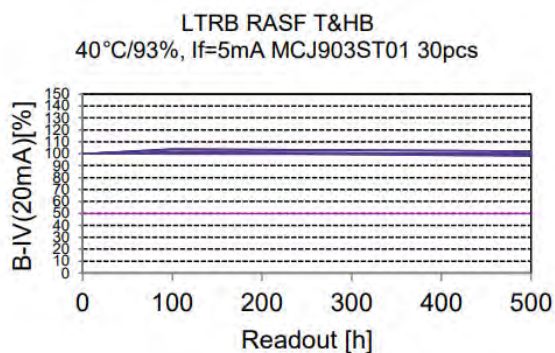




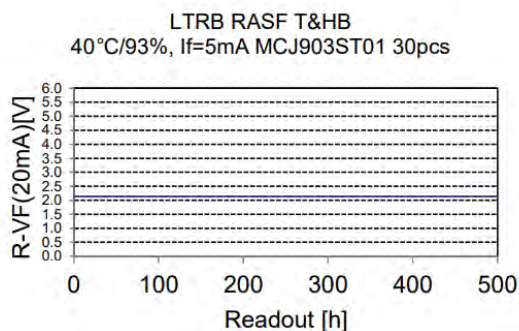
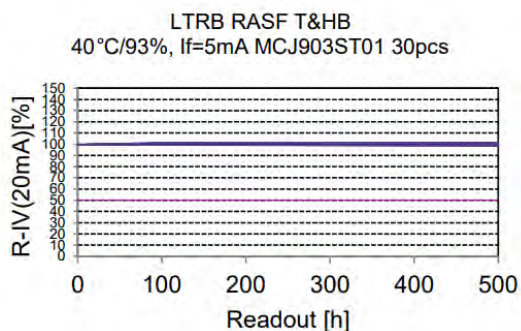
WHTOL 40°C/93%r.H; 5mA

Lot C - Eval

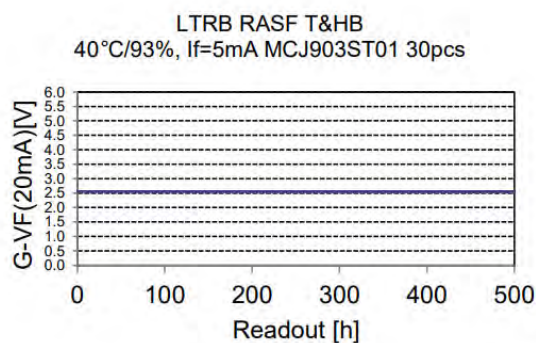
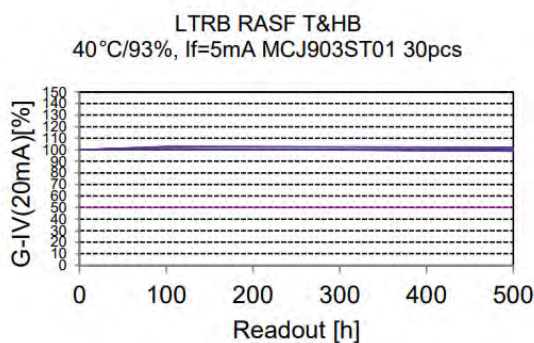
Blue chip



Red chip



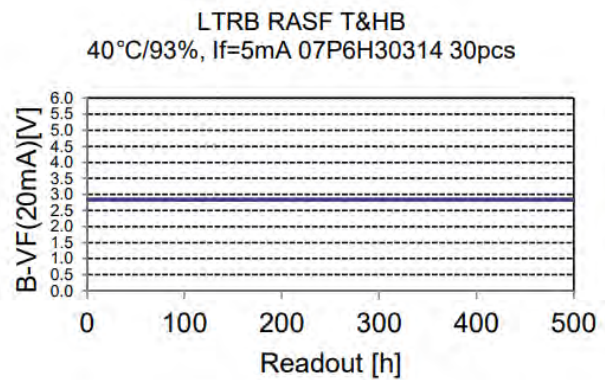
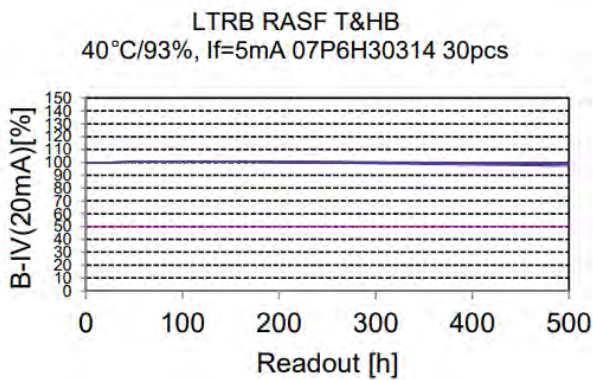
True green chip



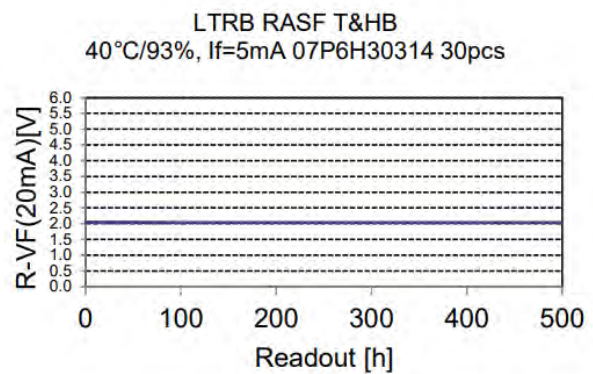
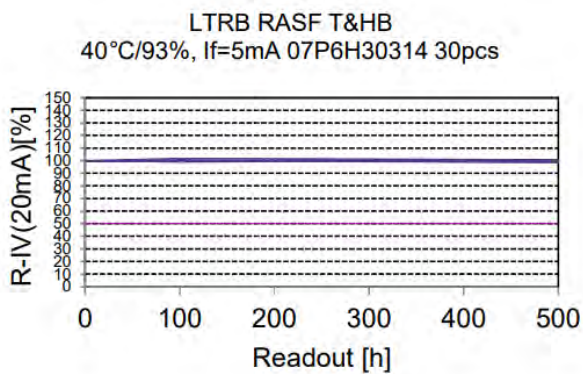
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Lot D - Control

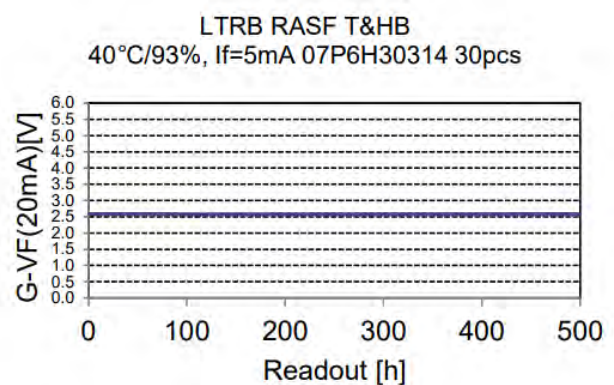
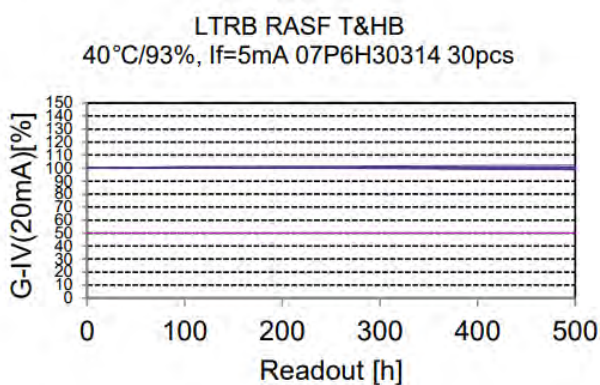
Blue chip



Red chip



True green chip

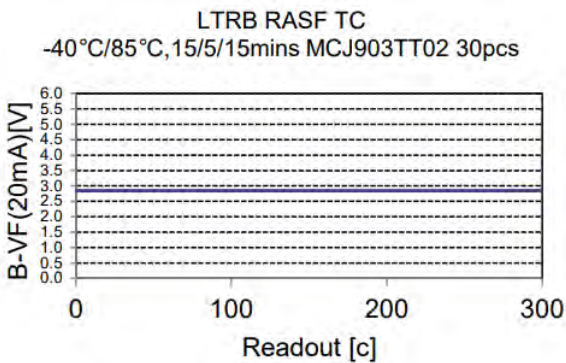
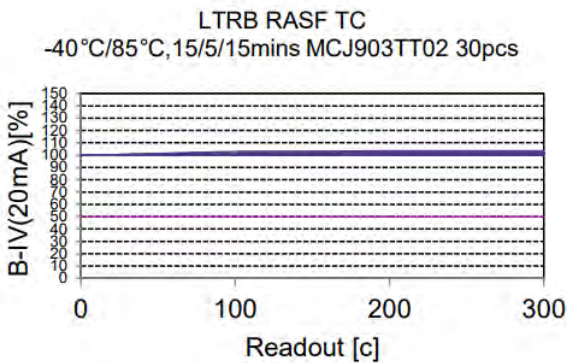




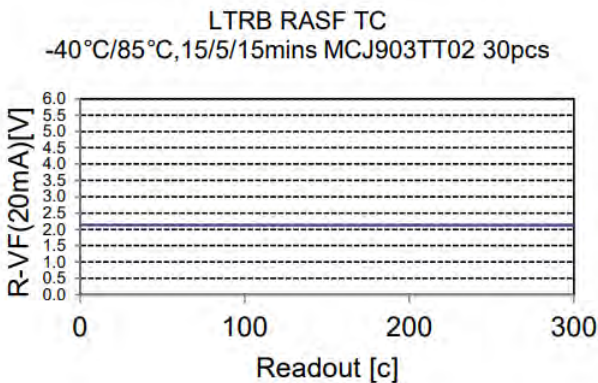
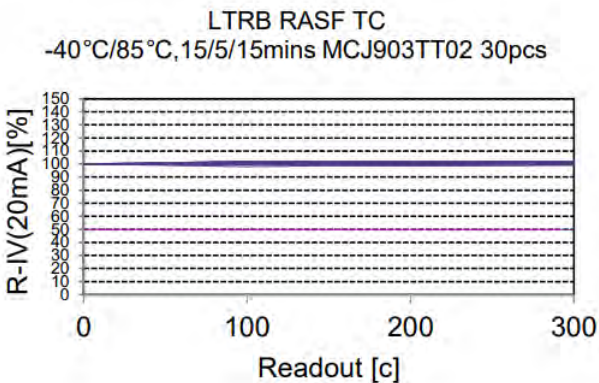
TC -40°C/85°C

Lot A - Eval

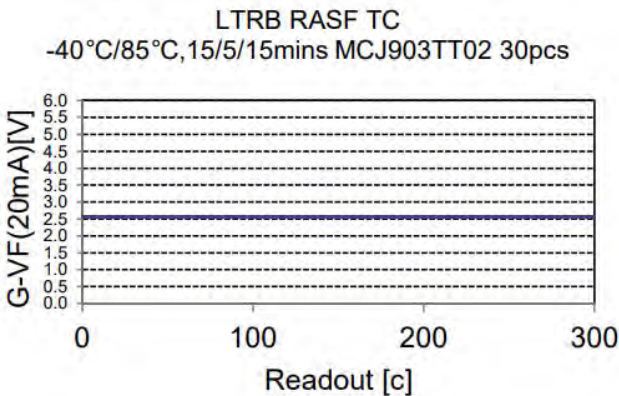
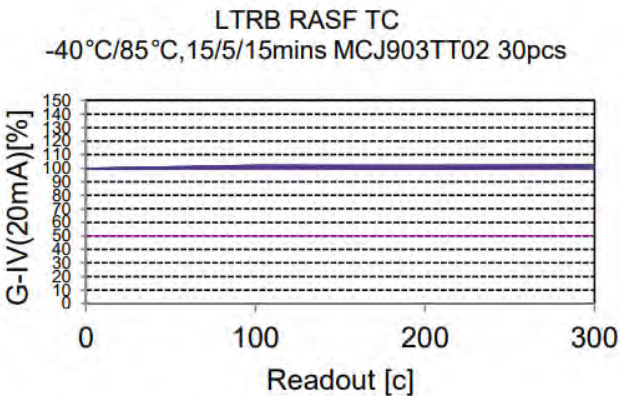
Blue chip



Red chip



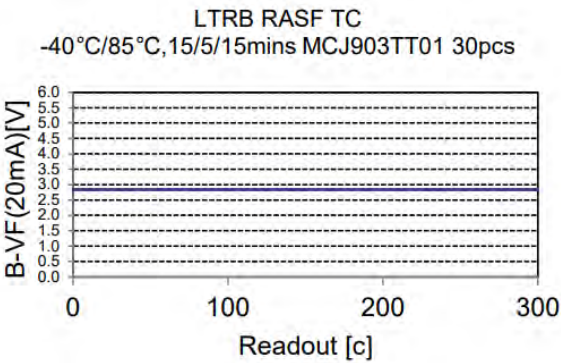
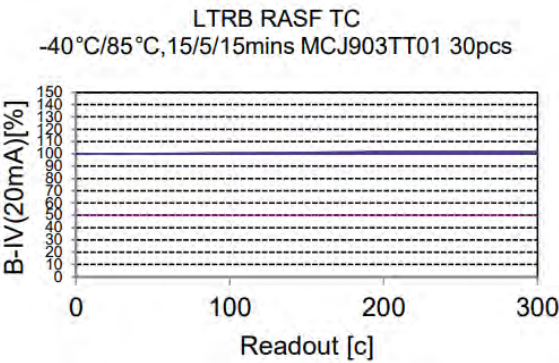
True green chip



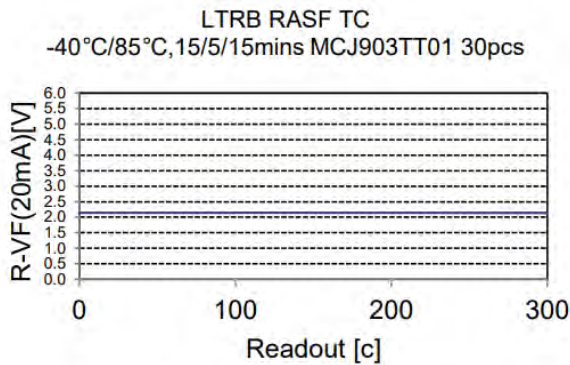
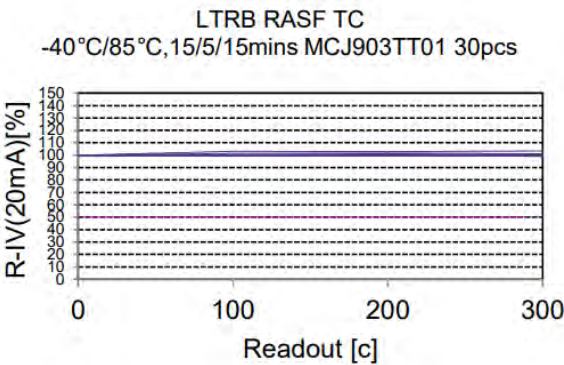
TC -40°C/85°C

Lot B - Eval

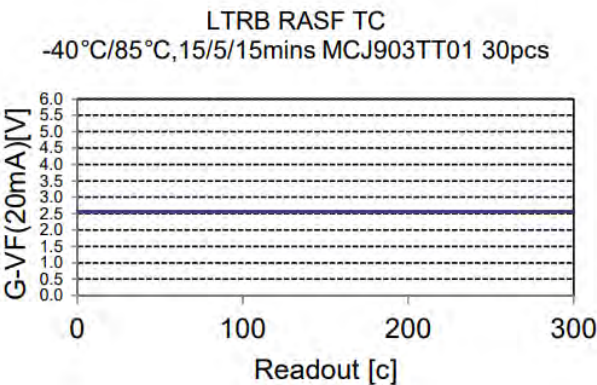
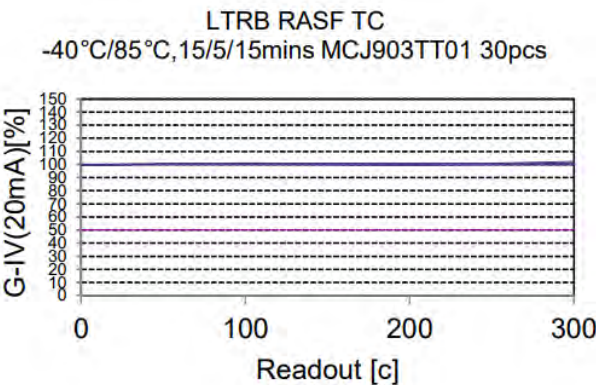
Blue chip



Red chip



True green chip

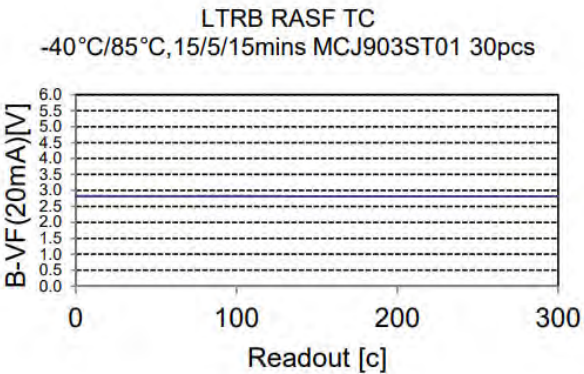
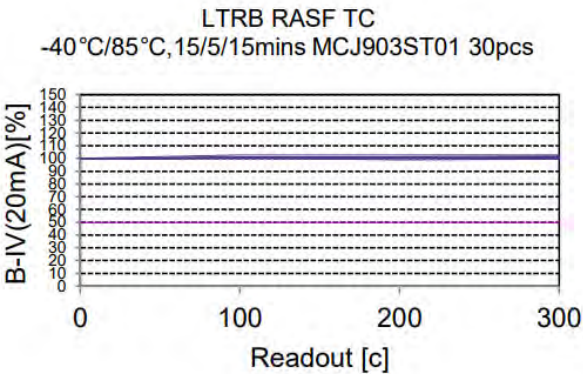




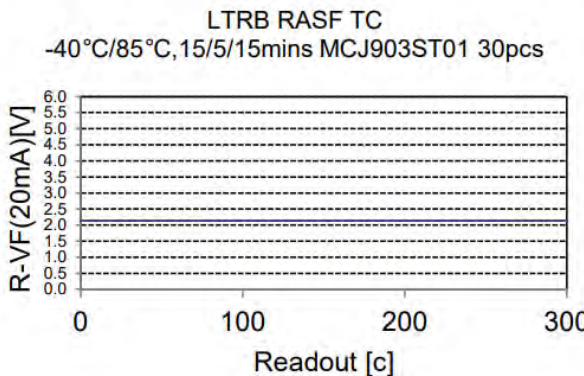
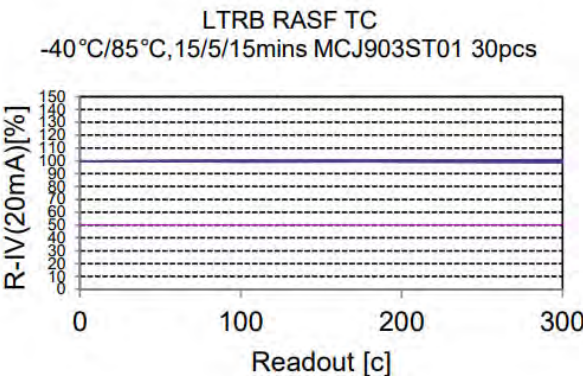
TC -40°C/85°C

Lot C - Eval

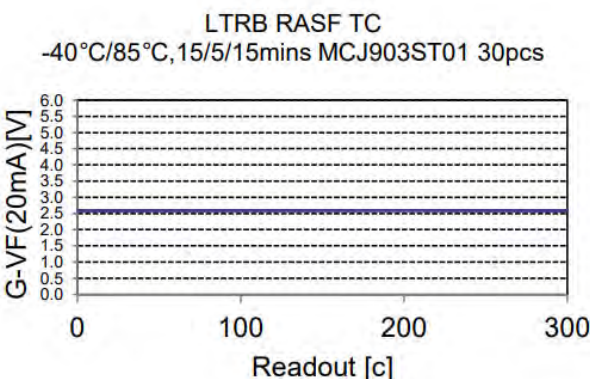
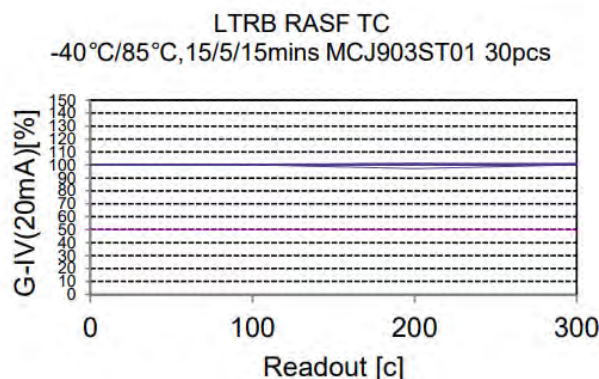
Blue chip



Red chip



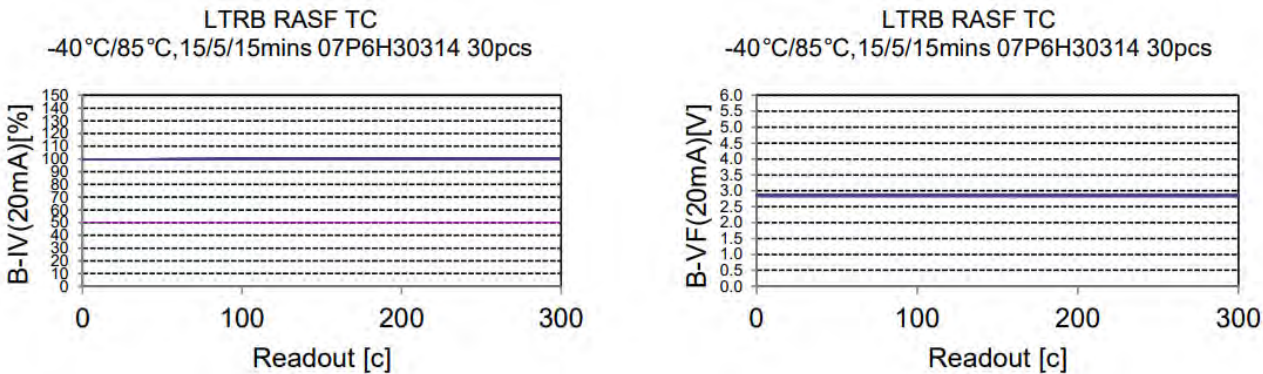
True green chip



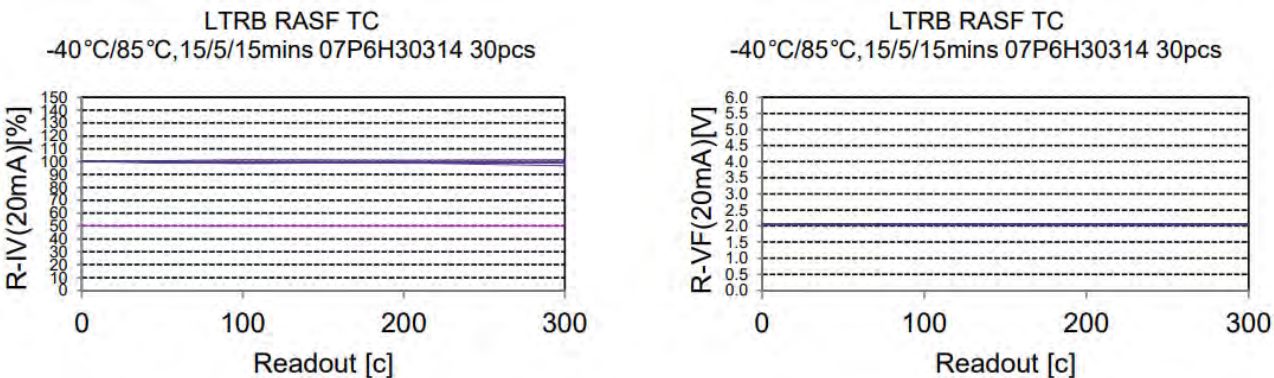
TC -40°C/85°C

Lot D - Control

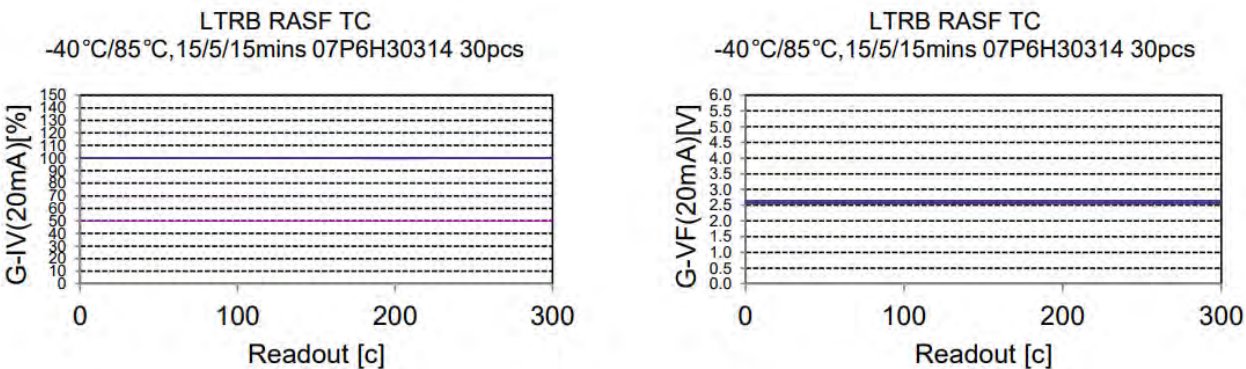
Blue chip



Red chip



True green chip

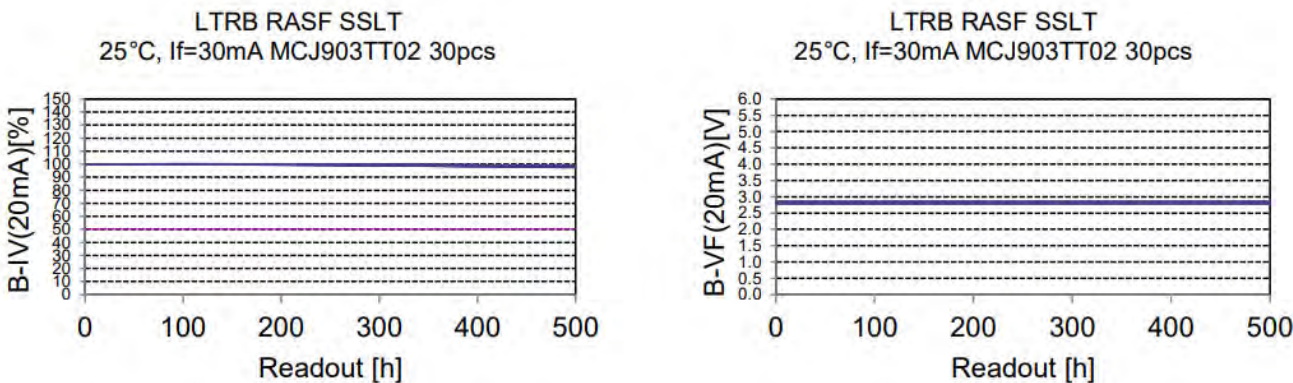




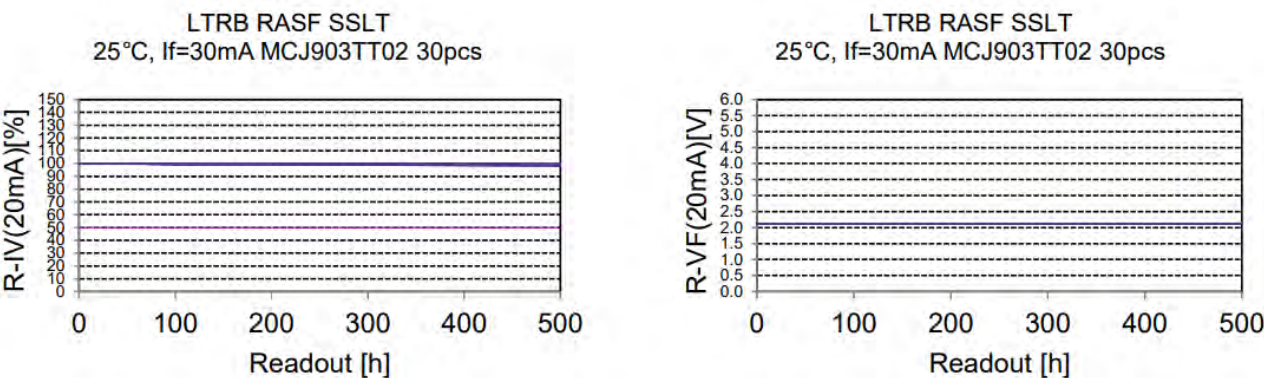
HTOL1 25°C/30mA

Lot A - Eval

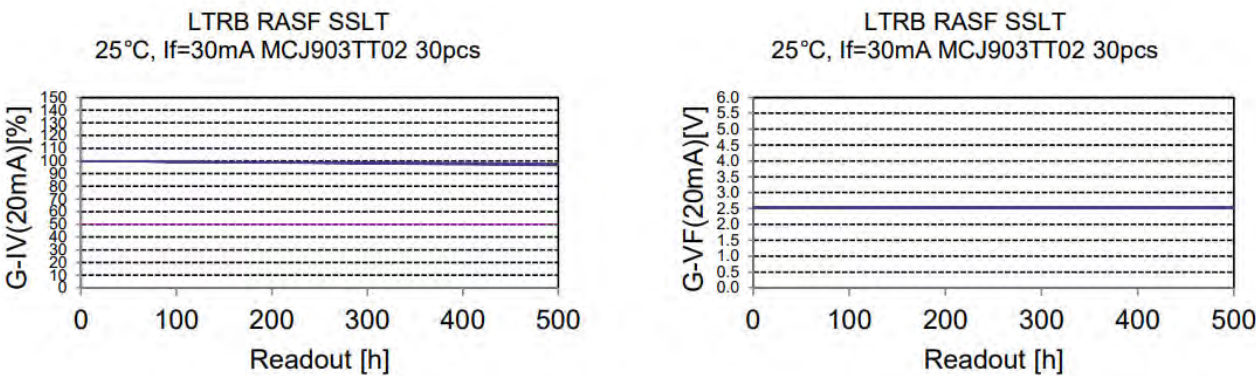
Blue chip



Red chip



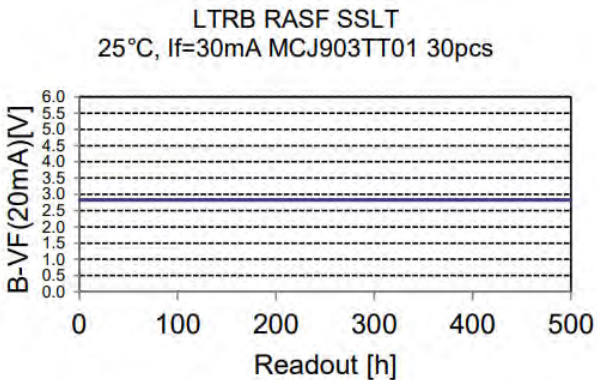
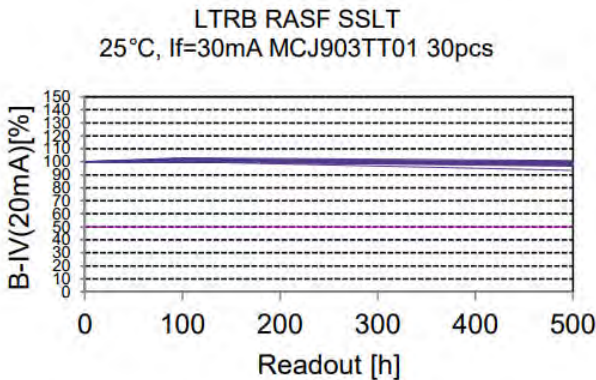
True green chip



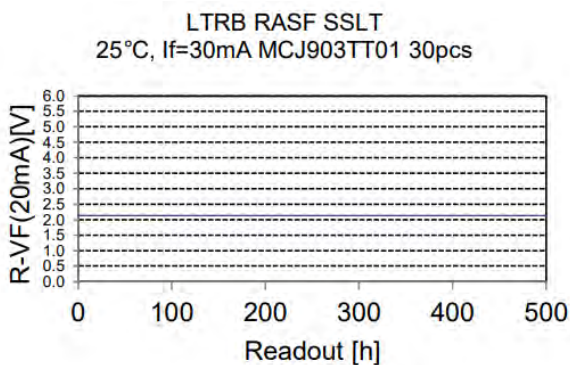
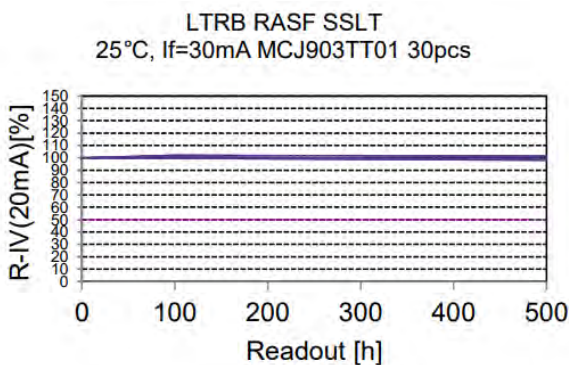
HTOL1 25°C/30mA

Lot B - Eval

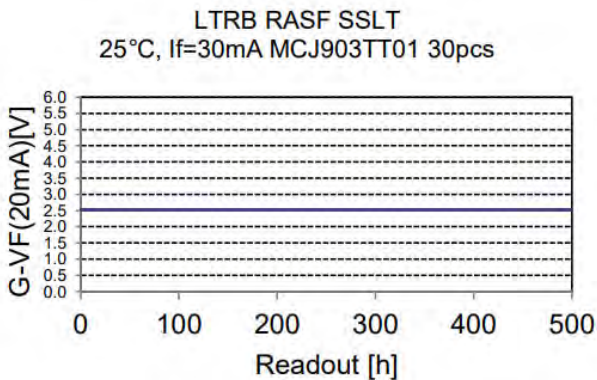
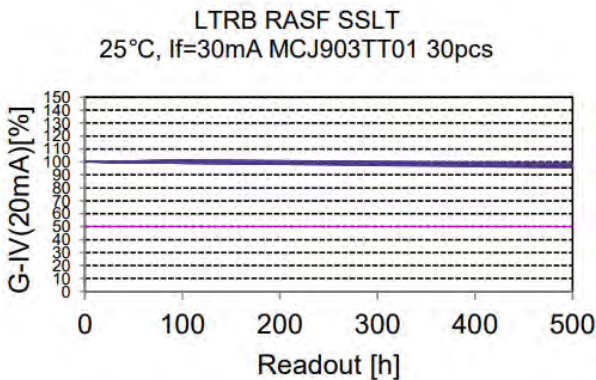
Blue chip



Red chip



True green chip

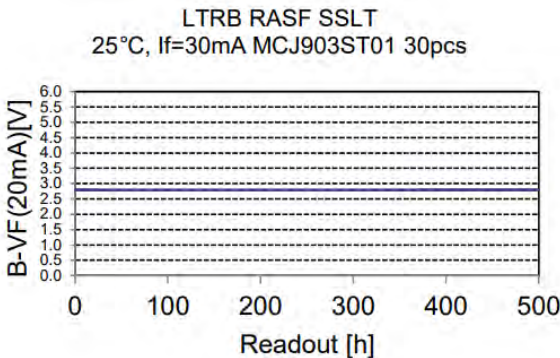
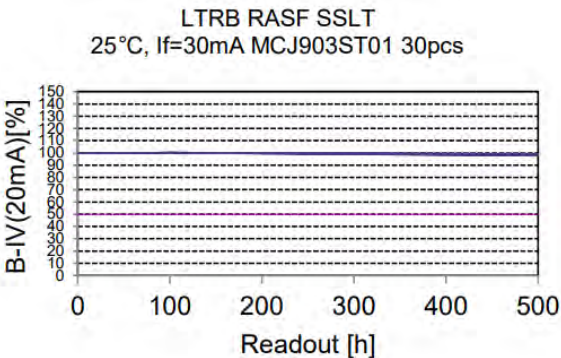




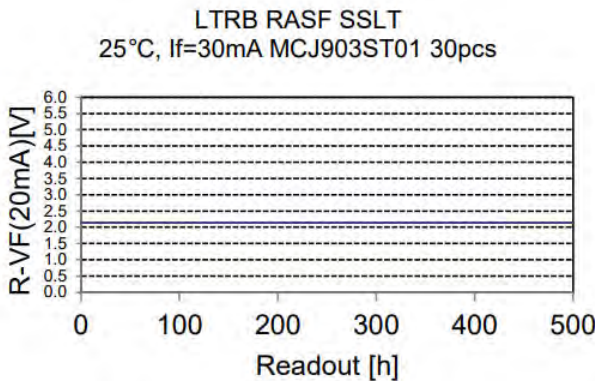
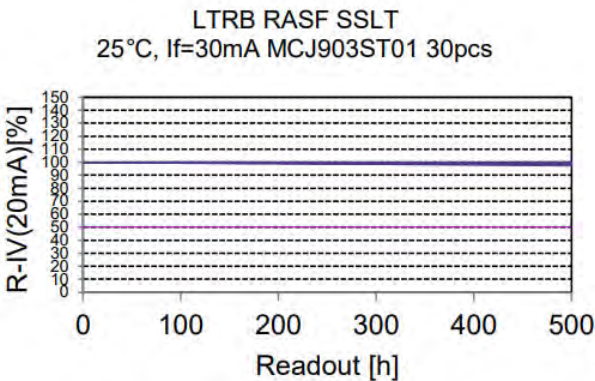
HTOL1 25°C/30mA

Lot C - Eval

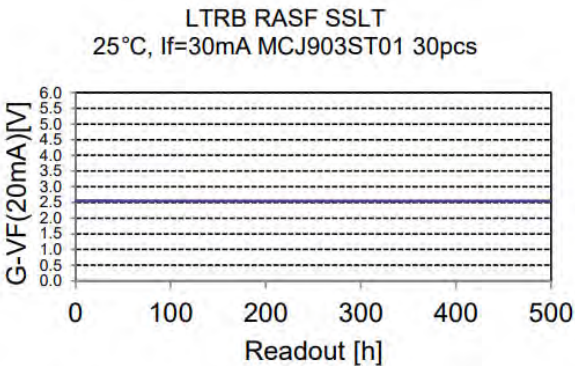
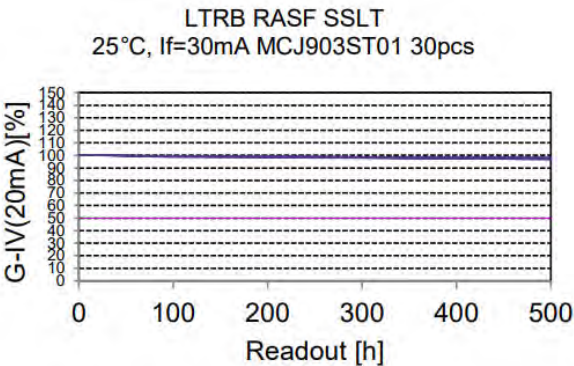
Blue chip



Red chip



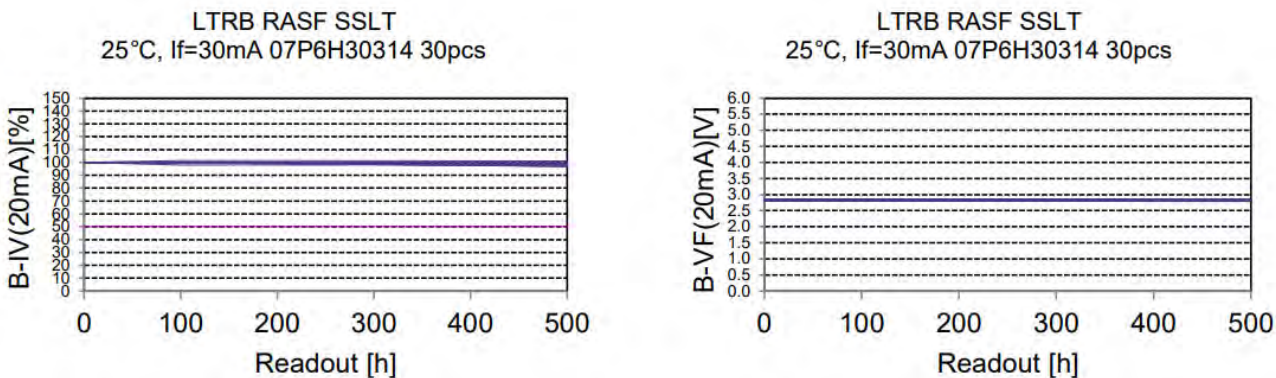
True green chip



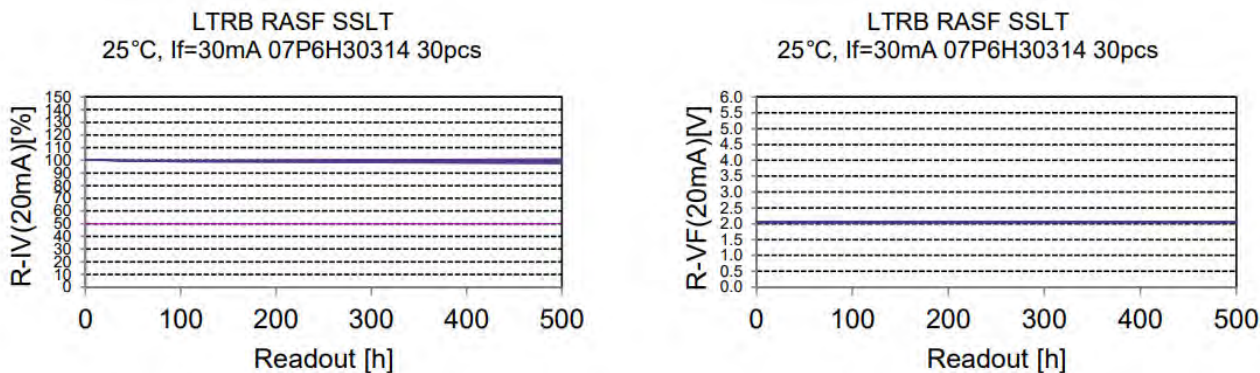
HTOL1 25°C/30mA

Lot D - Control

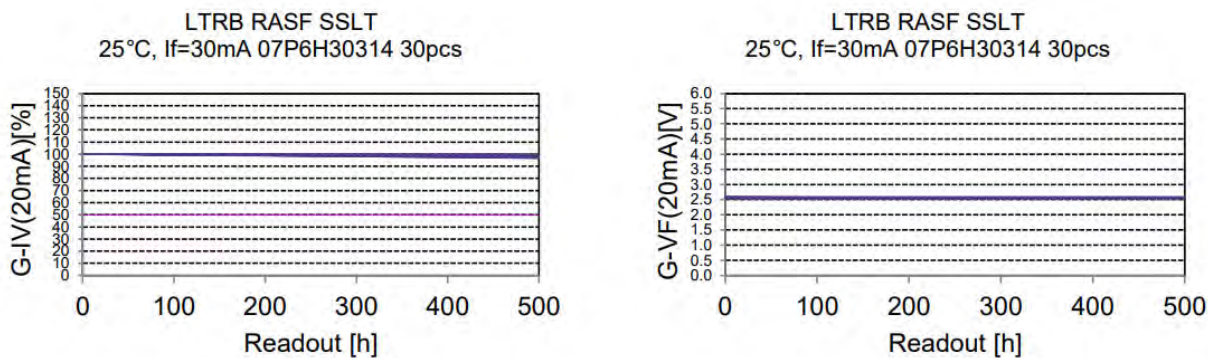
Blue chip



Red chip



True green chip

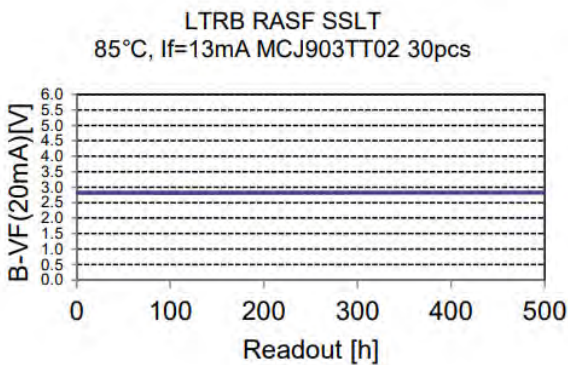
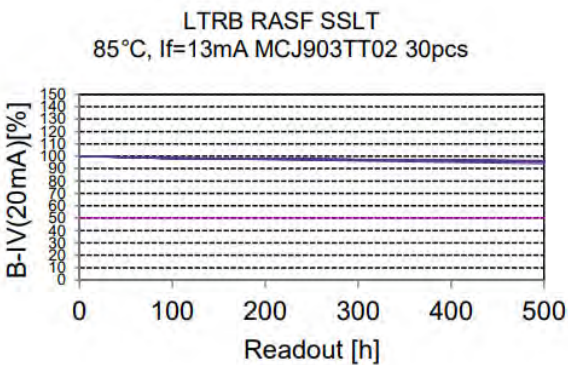




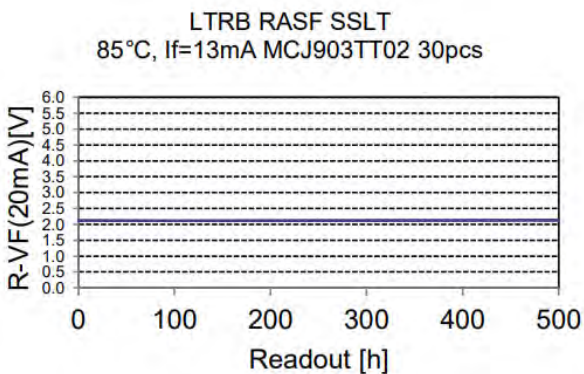
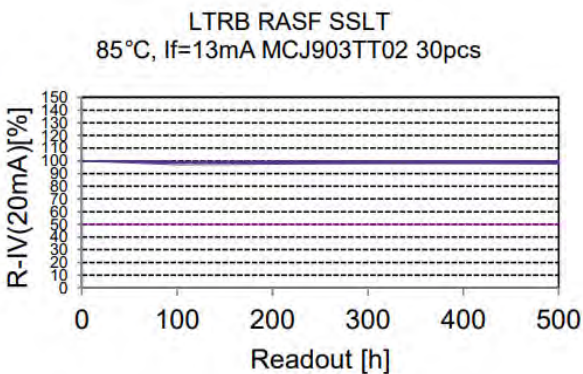
HTOL2 85°C/13mA

Lot A - Eval

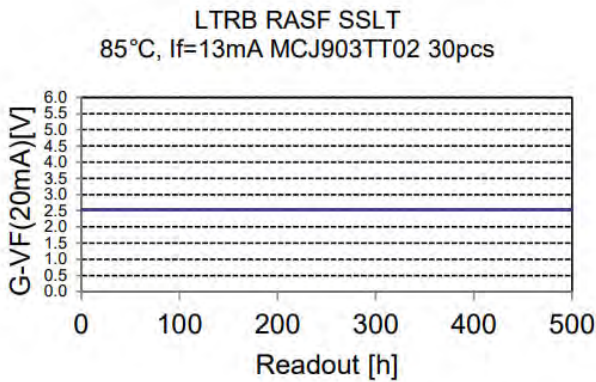
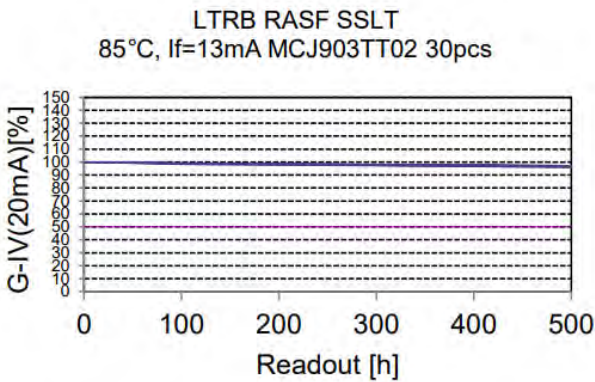
Blue chip



Red chip



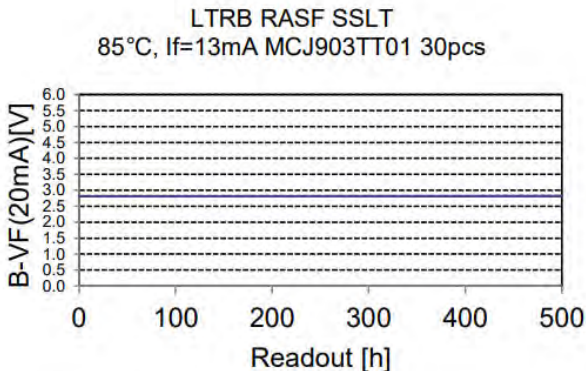
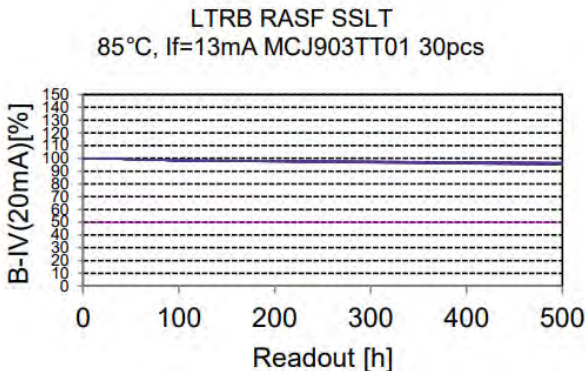
True green chip



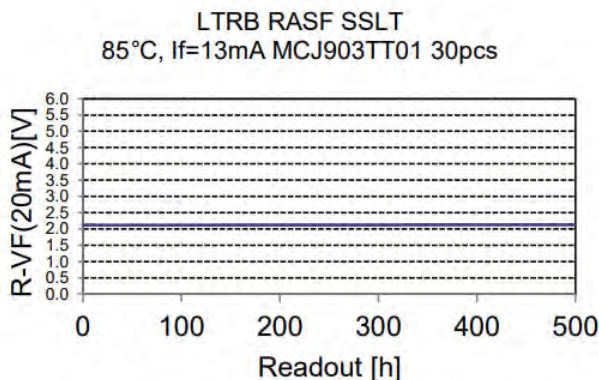
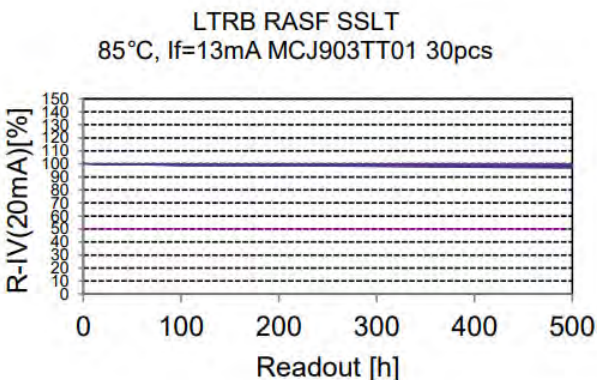
HTOL2 85°C/13mA

Lot B - Eval

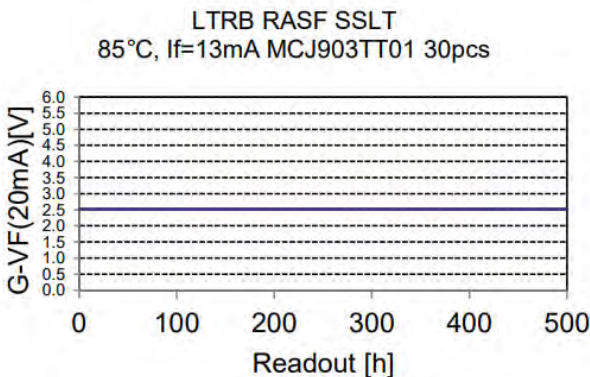
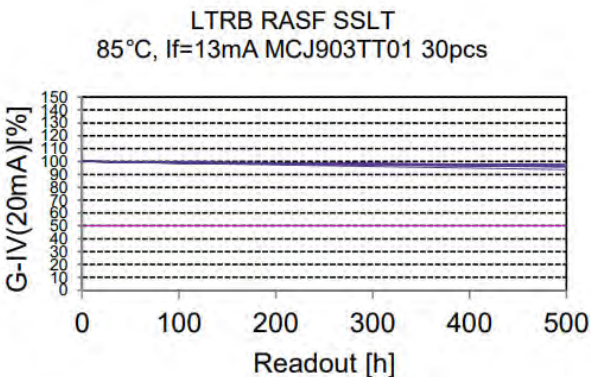
Blue chip



Red chip



True green chip

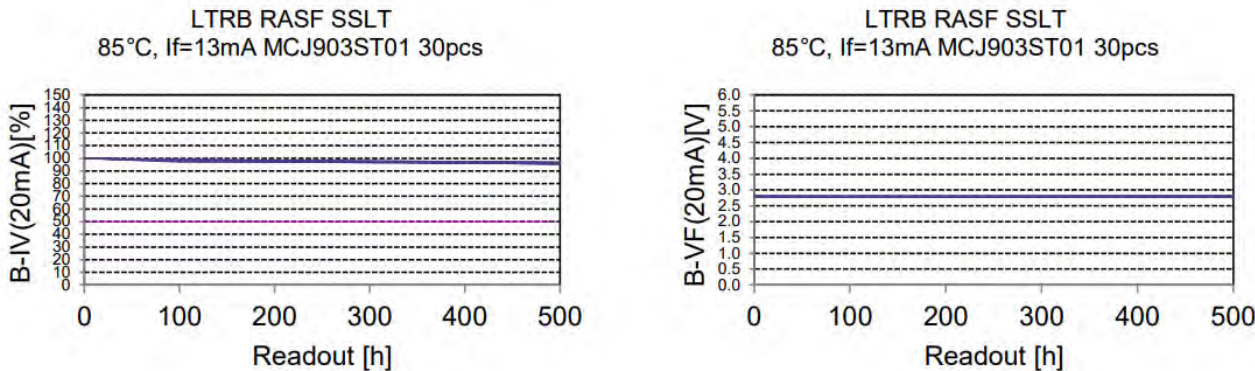




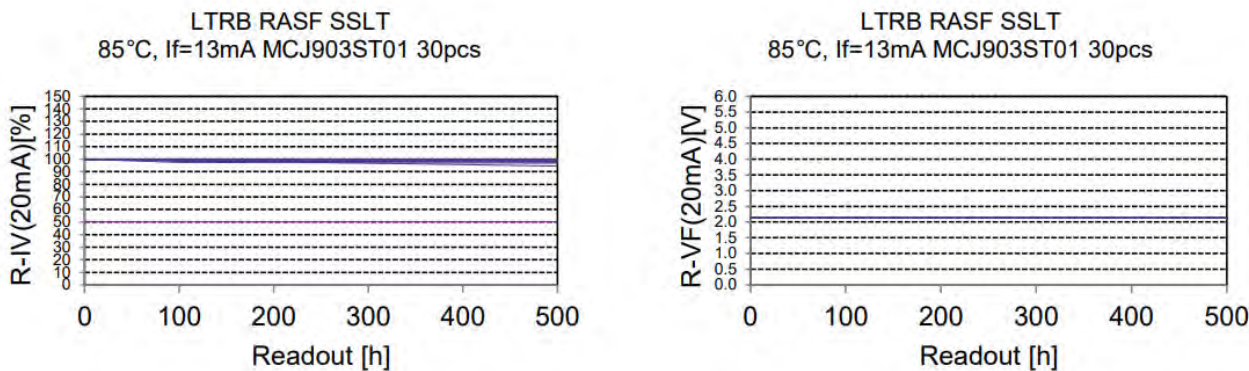
HTOL2 85°C/13mA

Lot C - Eval

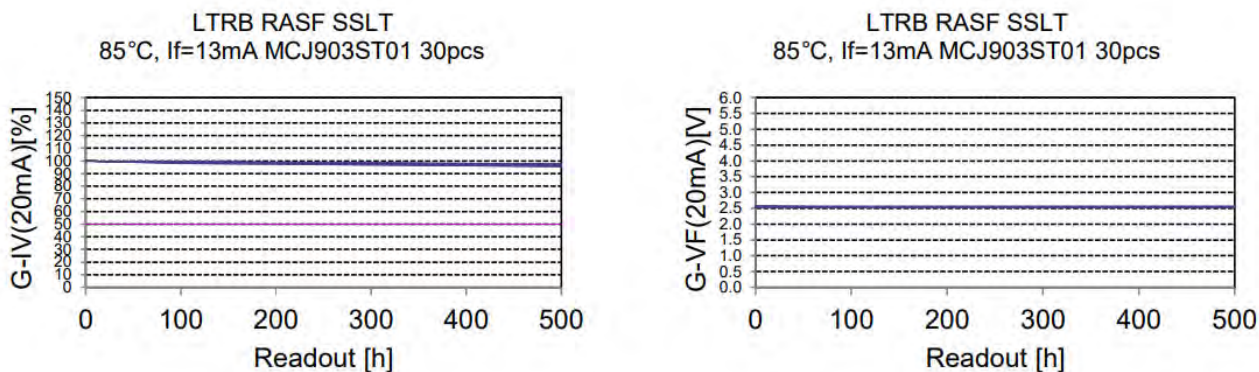
Blue chip



Red chip



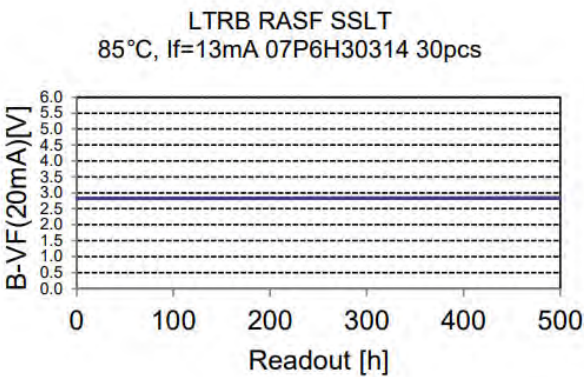
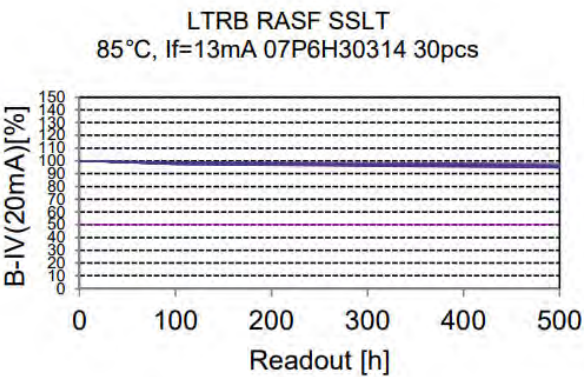
True green chip



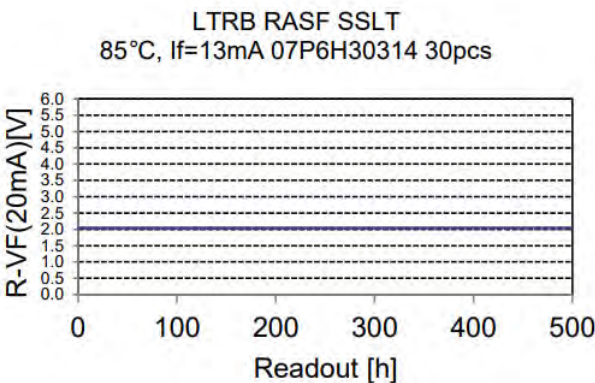
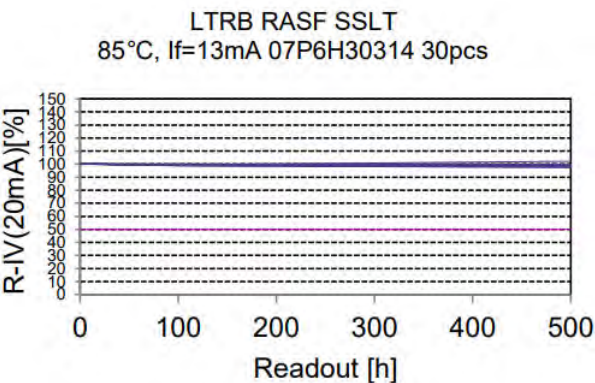
HTOL2 85°C/13mA

Lot D - Control

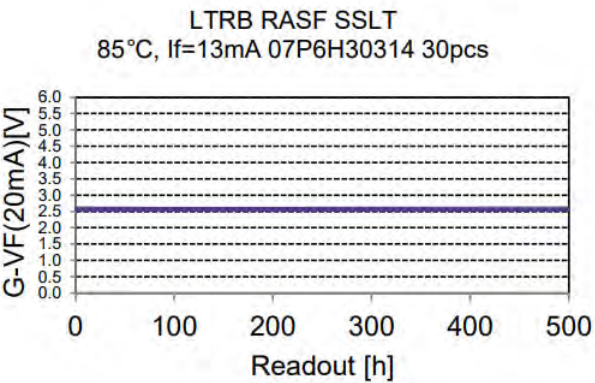
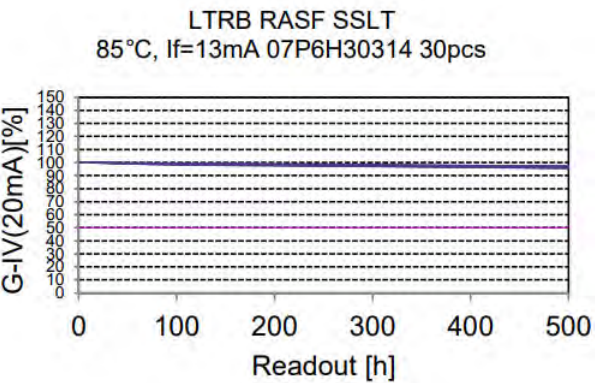
Blue chip



Red chip



True green chip



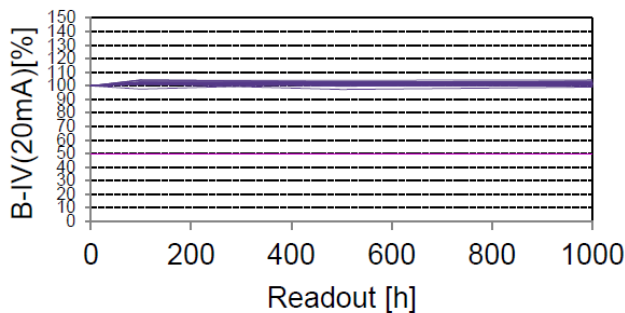


PLT 25°C/100mA/0.01ms/D=0.03

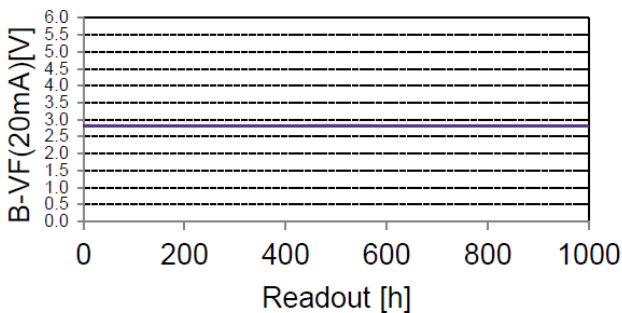
Lot A - Eval

Blue chip

LTRB RASF PLT  
25°C, If=100mA; MCJ903TT02 30pcs

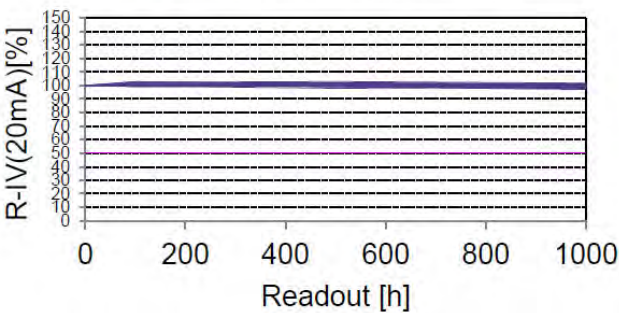


LTRB RASF PLT  
25°C, If=100mA; MCJ903TT02 30pcs

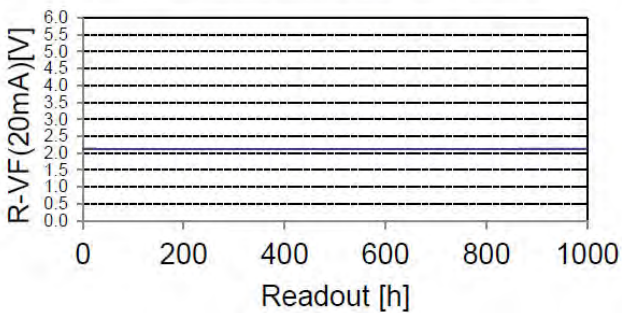


Red chip

LTRB RASF PLT  
25°C, If=100mA; MCJ903TT02 30pcs

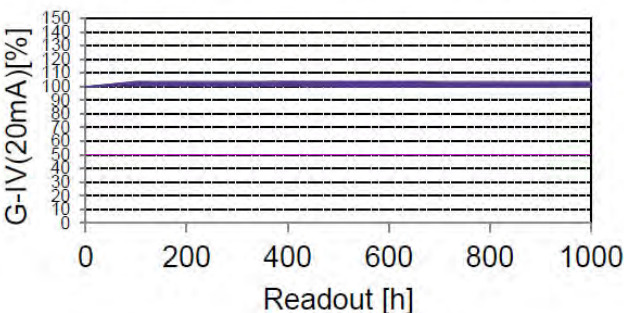


LTRB RASF PLT  
25°C, If=100mA; MCJ903TT02 30pcs

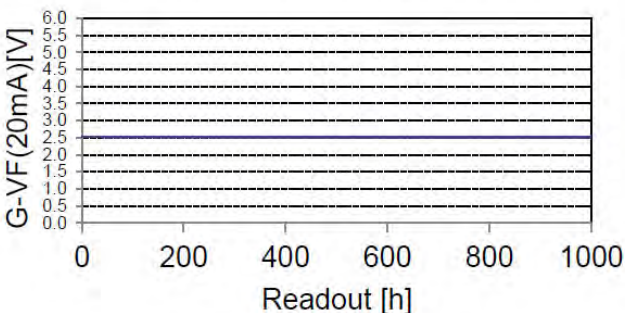


True green chip

LTRB RASF PLT  
25°C, If=100mA; MCJ903TT02 30pcs



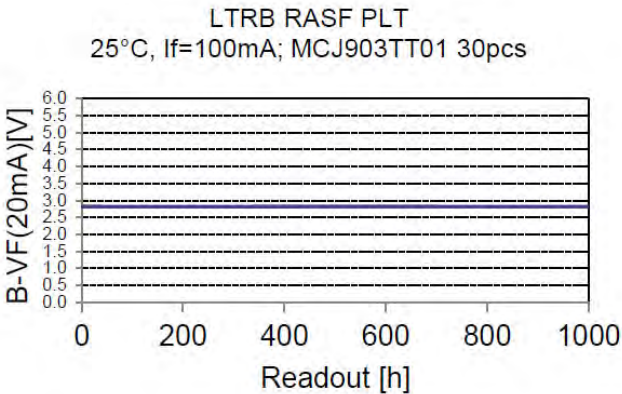
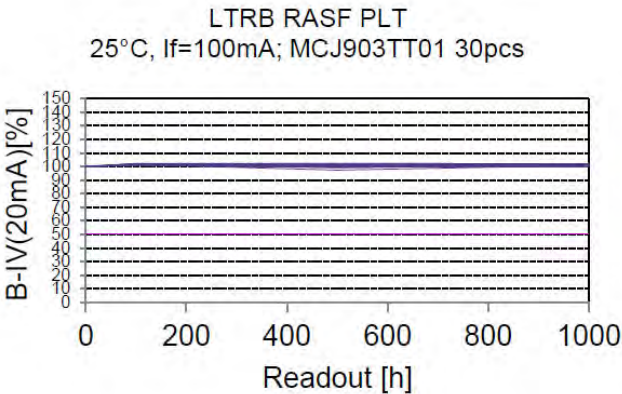
LTRB RASF PLT  
25°C, If=100mA; MCJ903TT02 30pcs



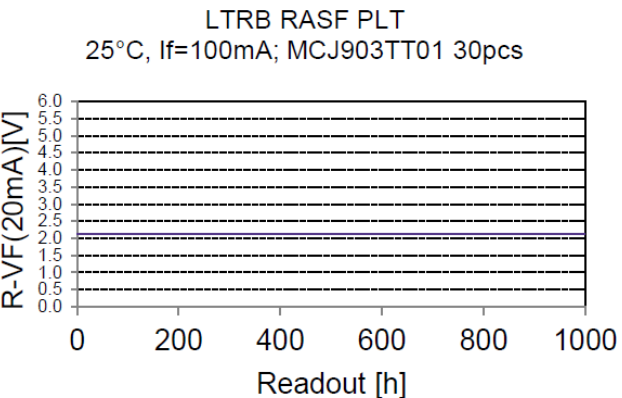
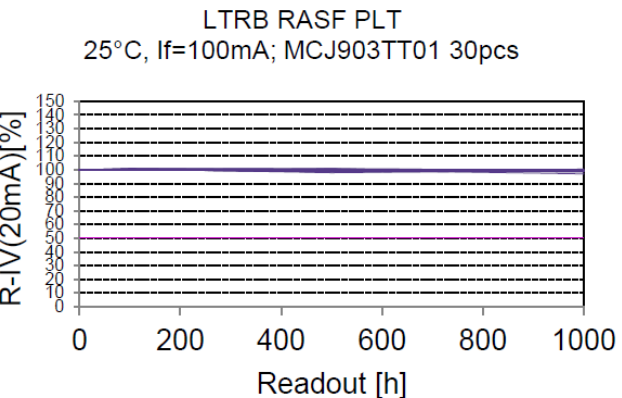
PLT 25°C/100mA/0.01ms/D=0.03

Lot B - Eval

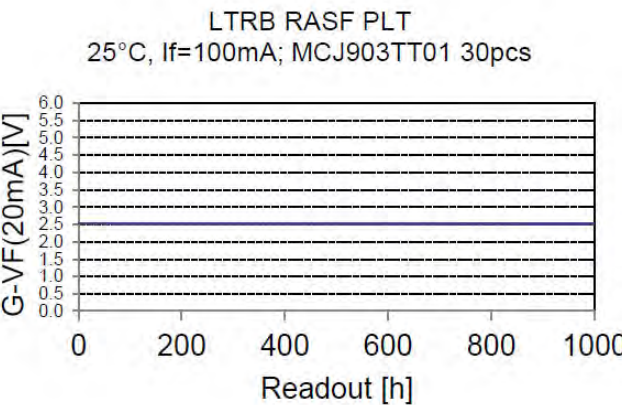
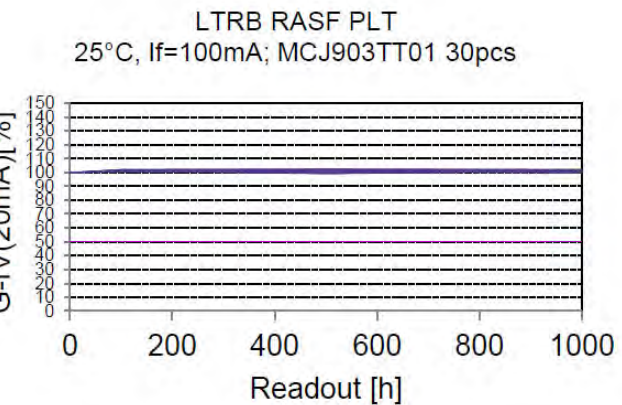
Blue chip



Red chip



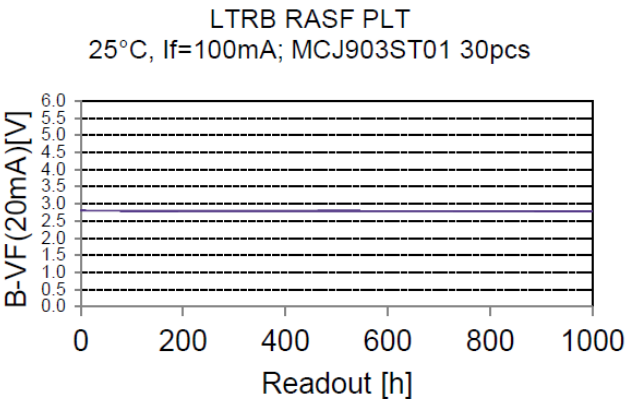
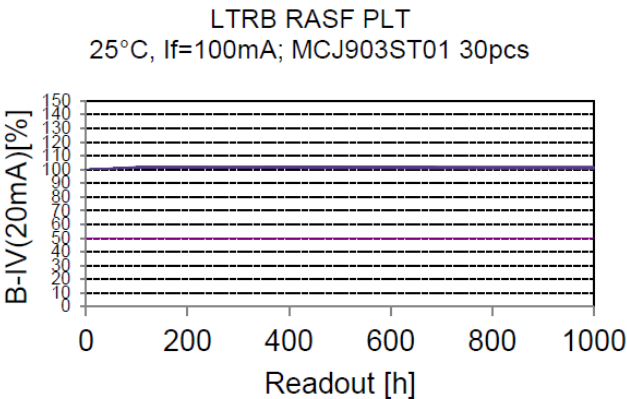
True green chip



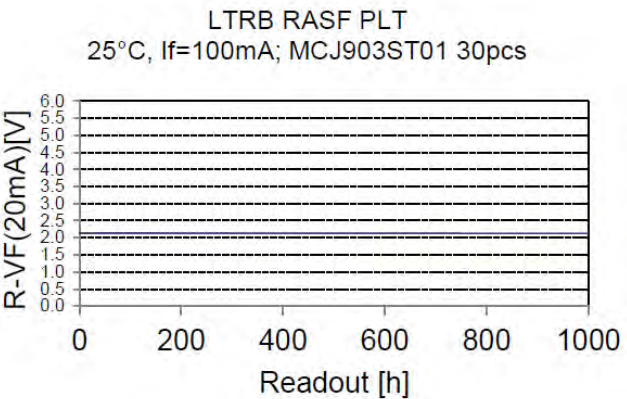
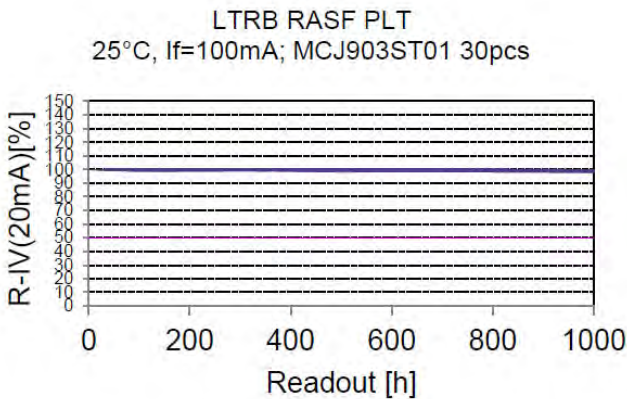
PLT 25°C/100mA/0.01ms/D=0.03

Lot C - Eval

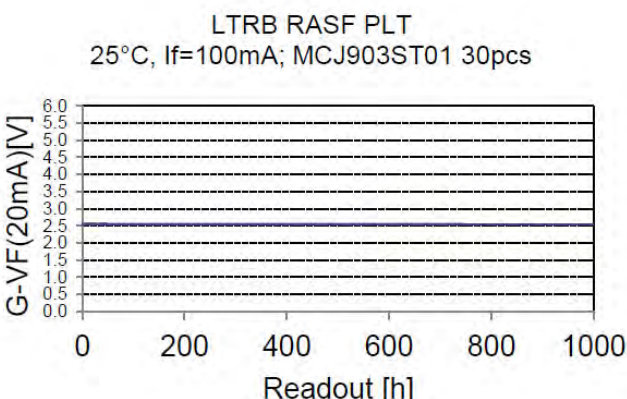
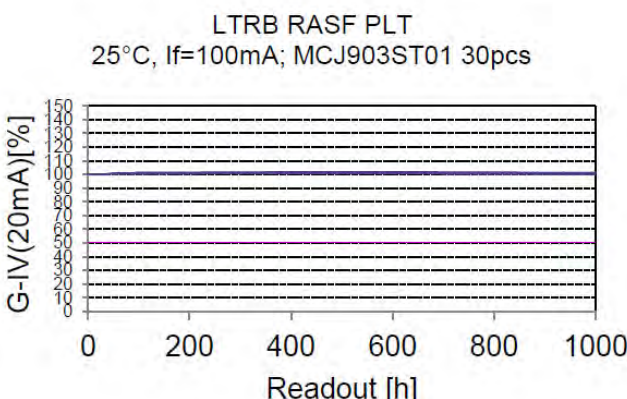
Blue chip



Red chip



True green chip



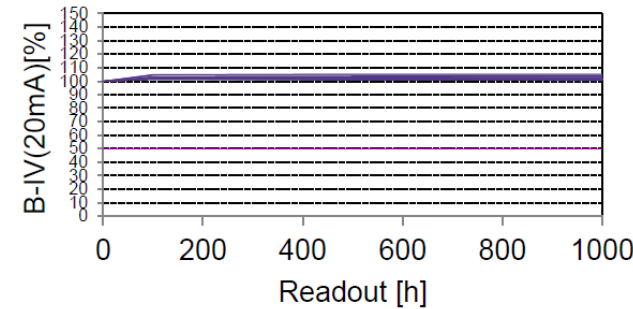


PLT 25°C/100mA/0.01ms/D=0.03

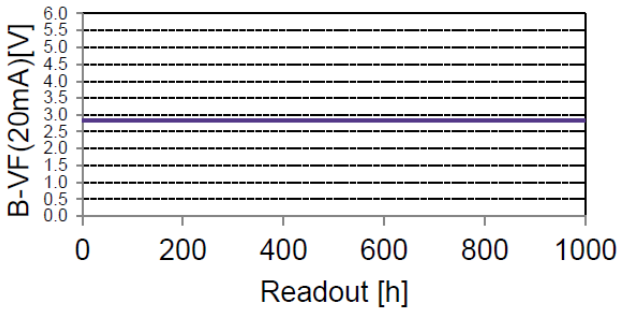
Lot D - Control

Blue chip

LTRB RASF PLT  
25°C, If=100mA; 07P6H30314 30pcs

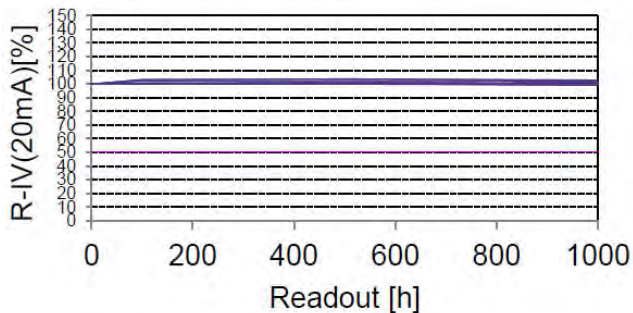


LTRB RASF PLT  
25°C, If=100mA; 07P6H30314 30pcs

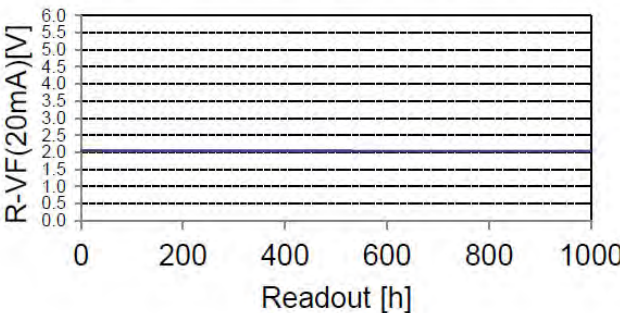


Red chip

LTRB RASF PLT  
25°C, If=100mA; 07P6H30314 30pcs

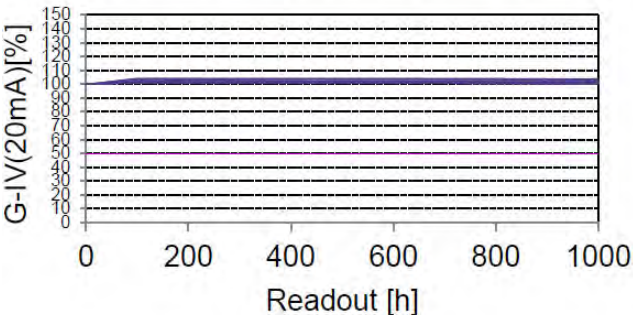


LTRB RASF PLT  
25°C, If=100mA; 07P6H30314 30pcs

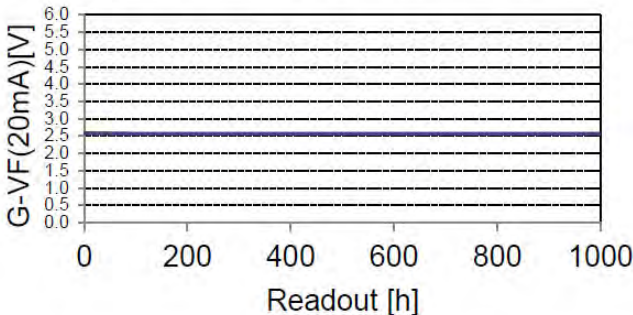


True green chip

LTRB RASF PLT  
25°C, If=100mA; 07P6H30314 30pcs



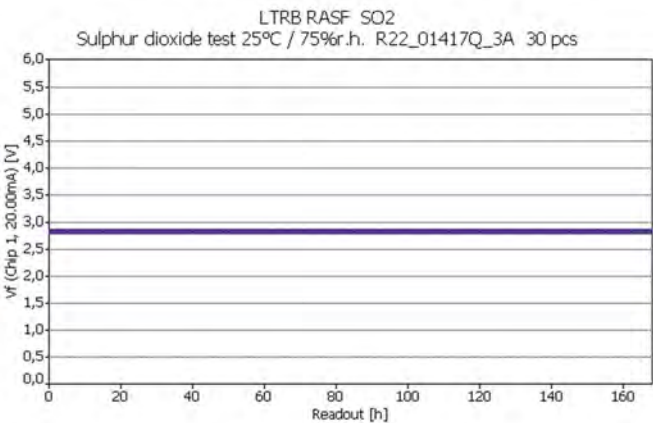
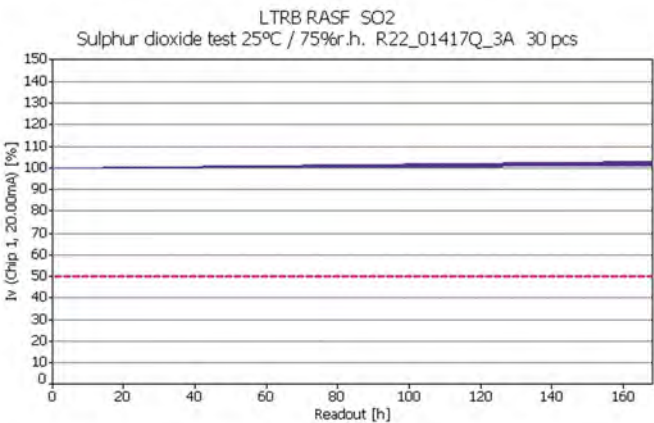
LTRB RASF PLT  
25°C, If=100mA; 07P6H30314 30pcs



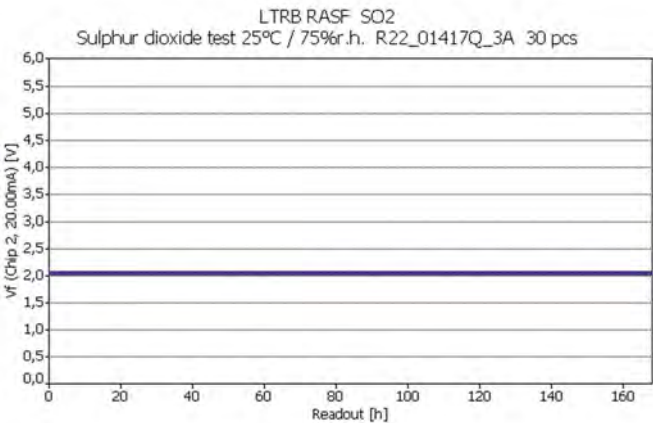
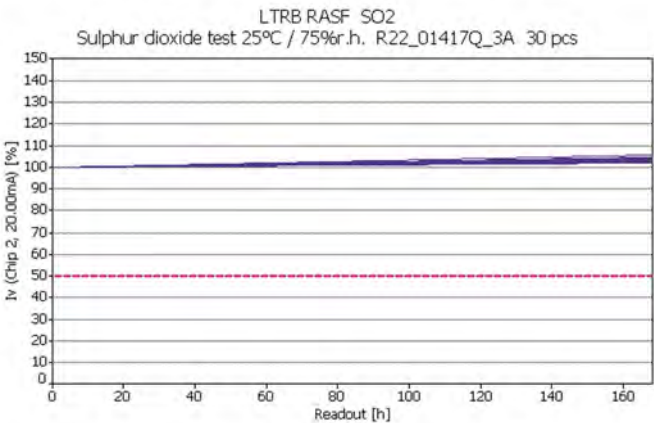
SO<sub>2</sub> 25°C/75% r.H.

Lot A - Eval

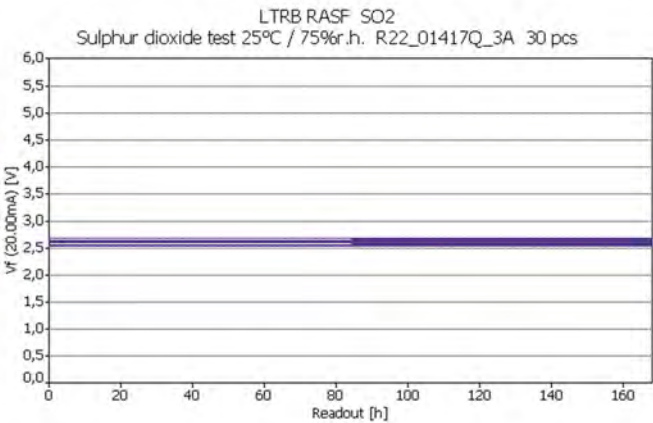
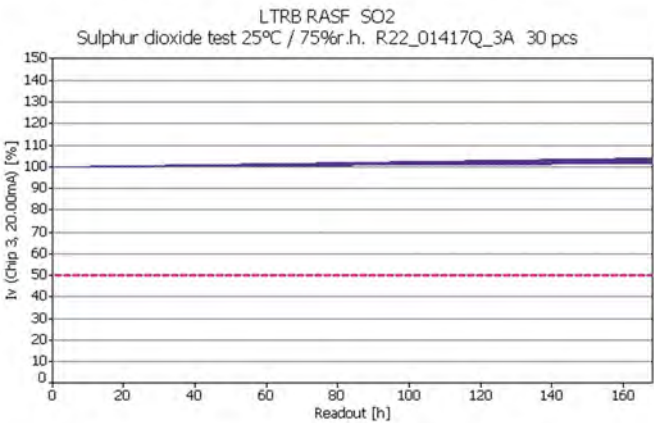
Blue chip



Red chip



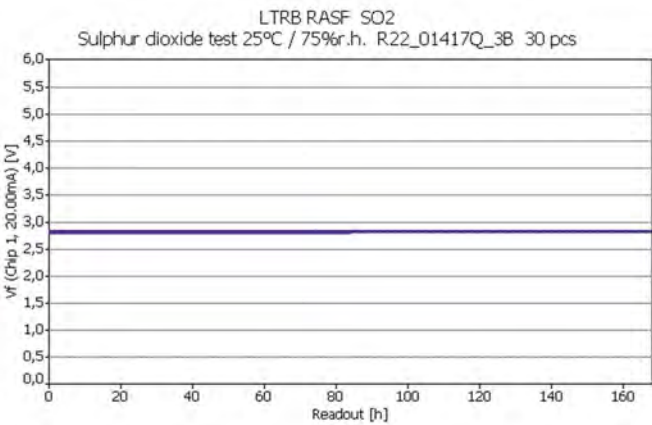
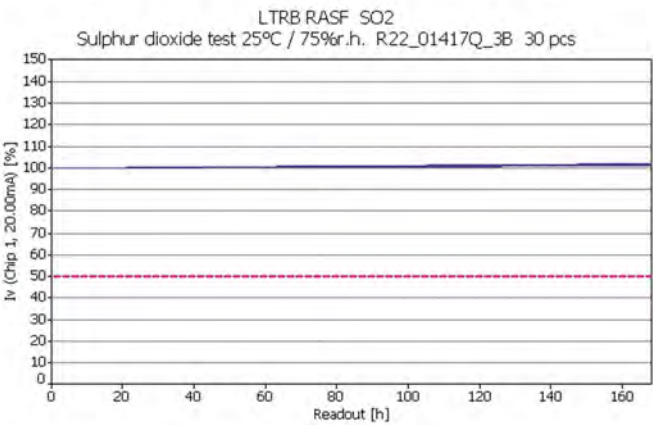
True green chip



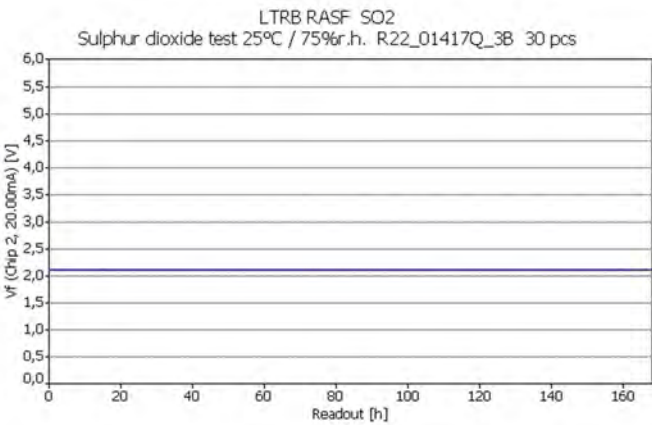
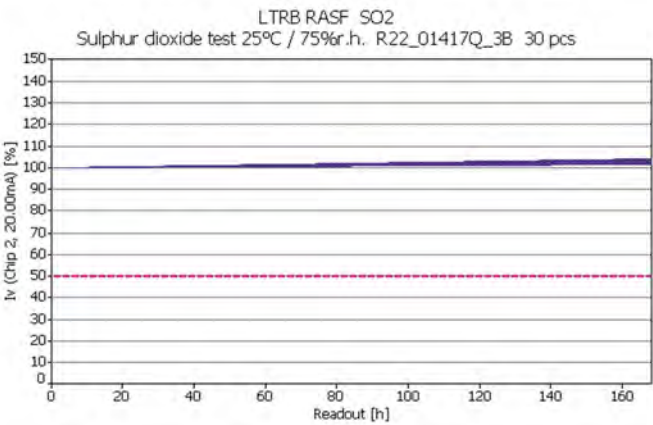
SO<sub>2</sub> 25°C/75% r.H.

Lot B - Eval

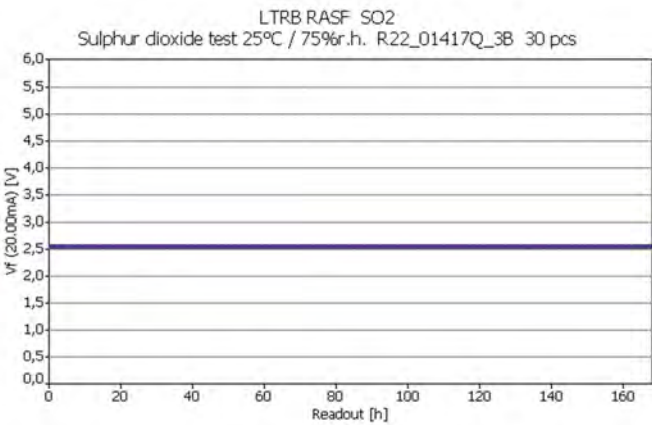
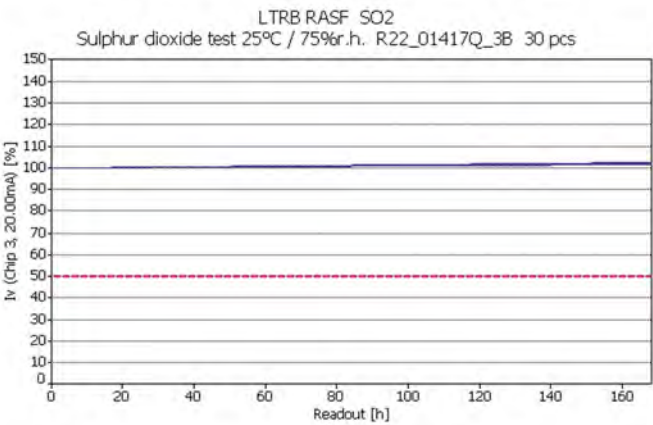
Blue chip



Red chip



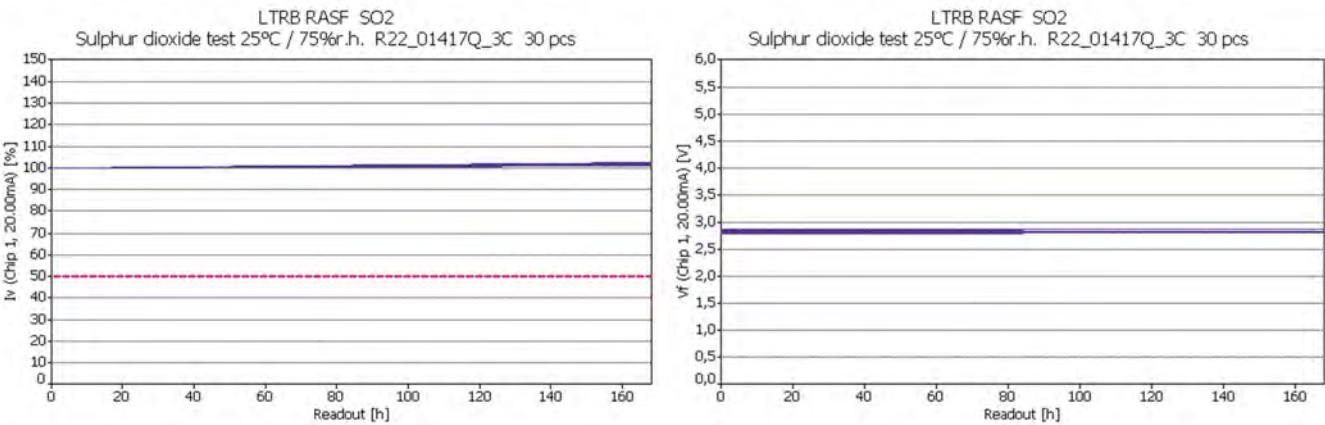
True green chip



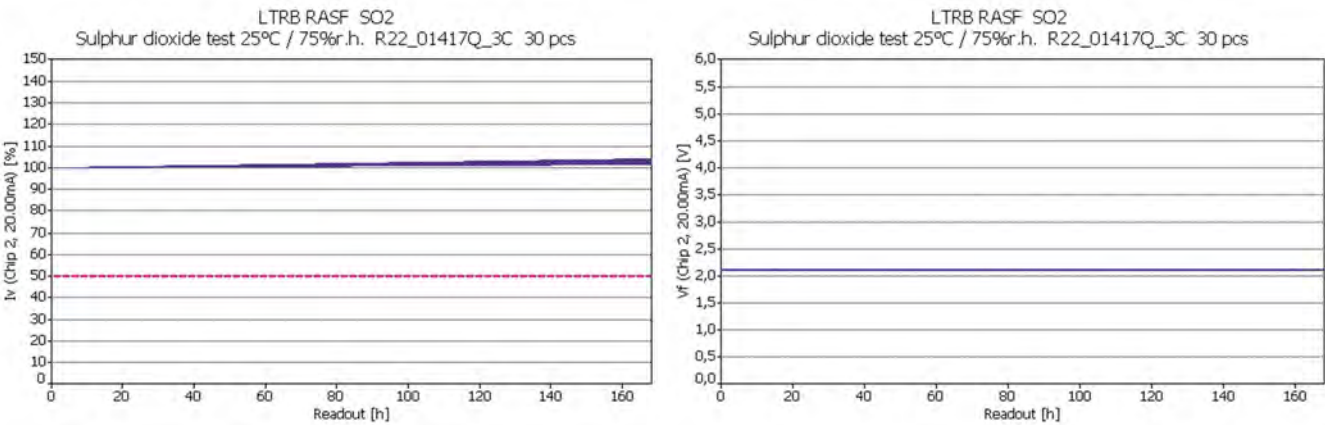
SO<sub>2</sub> 25°C/75% r.H.

Lot C - Eval

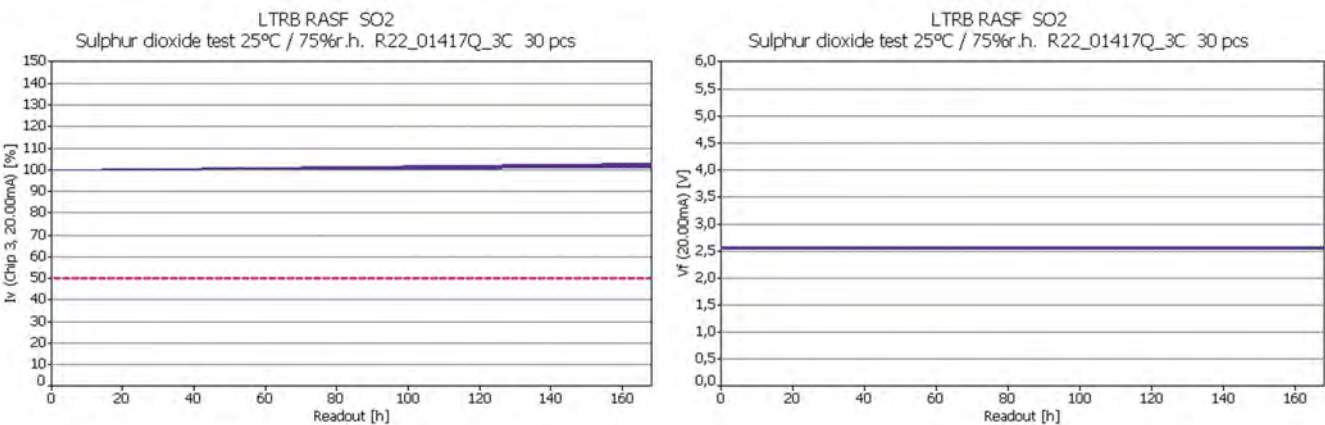
Blue chip



Red chip



True green chip

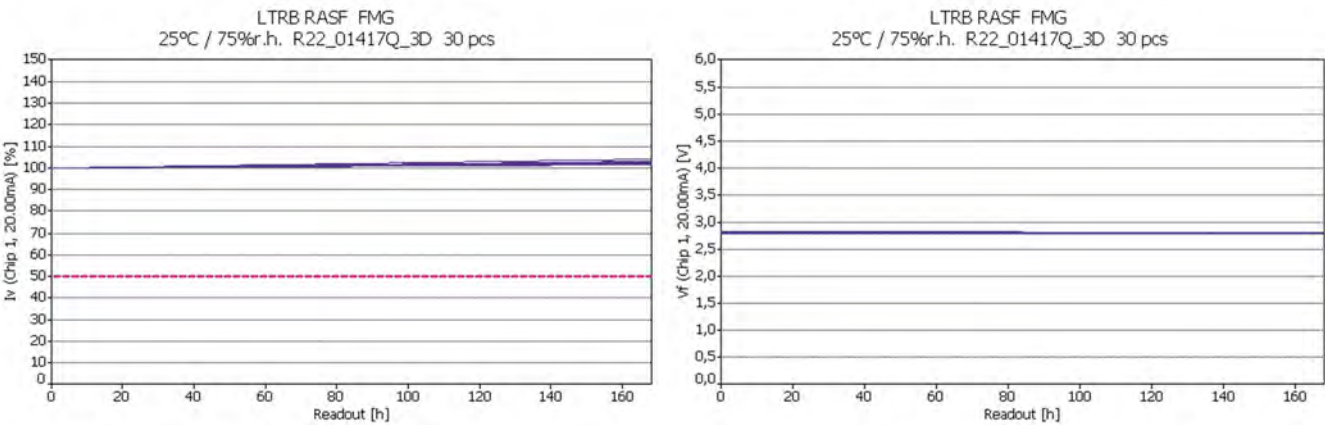




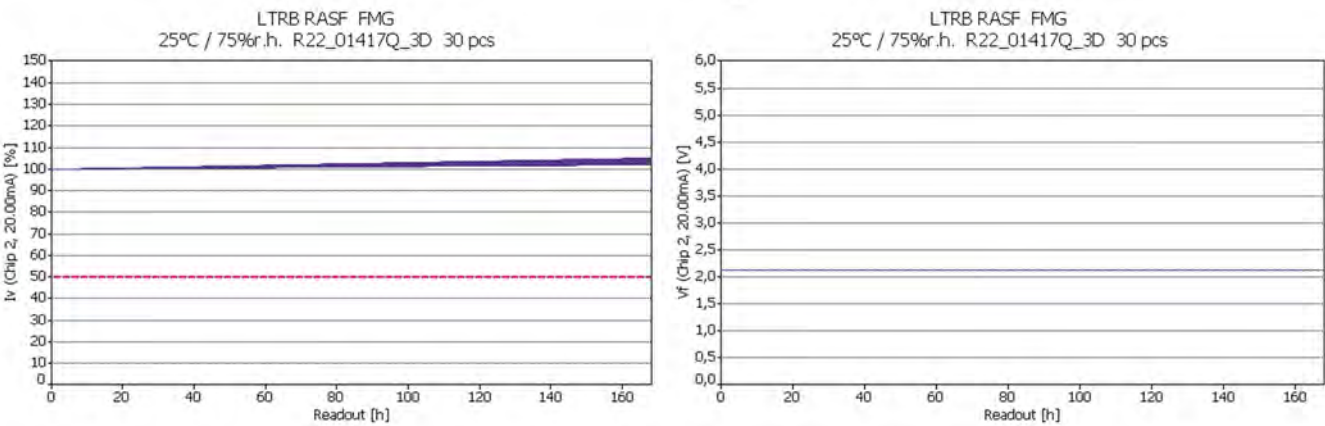
SO<sub>2</sub> 25°C/75% r.H.

Lot D - Control

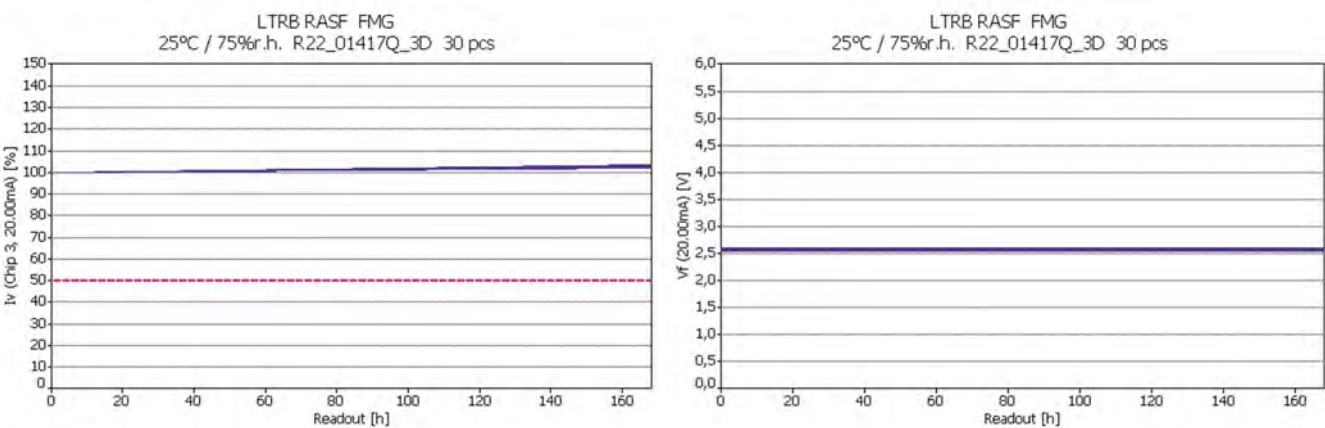
Blue chip



Red chip



True green chip

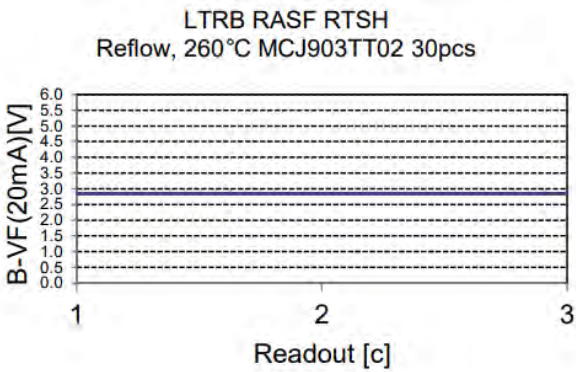
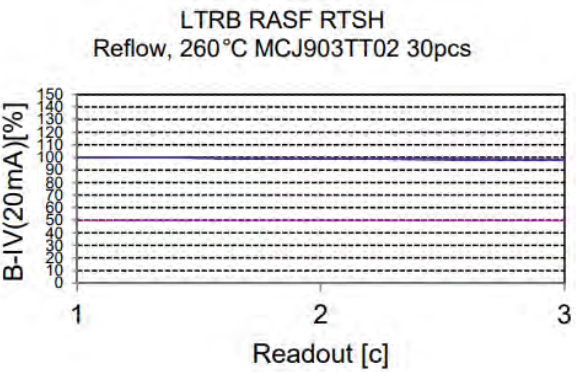




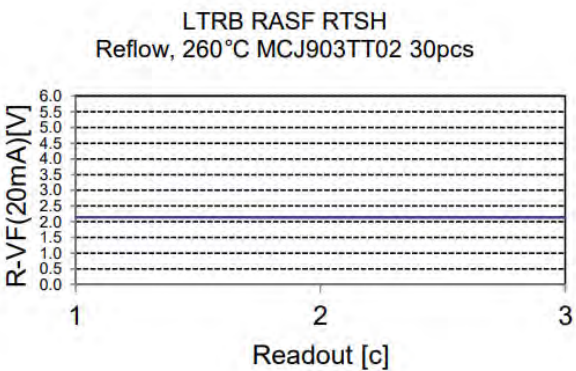
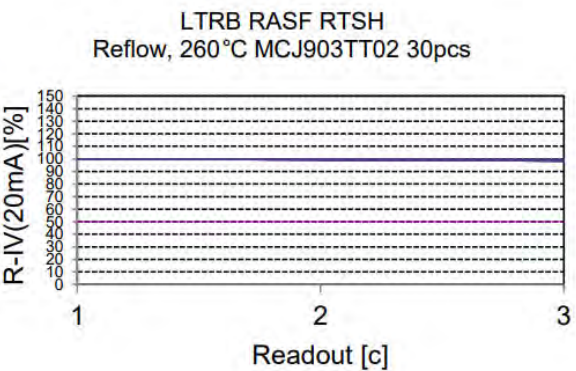
RSH Resistance to Solder Heat

Lot A - Eval

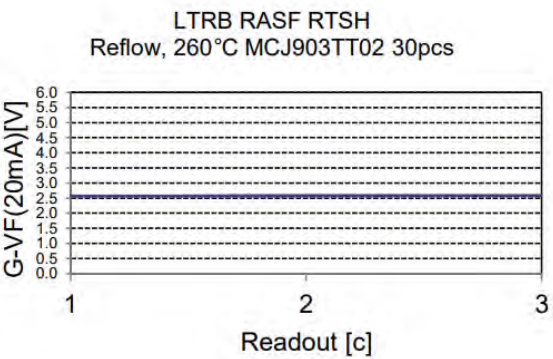
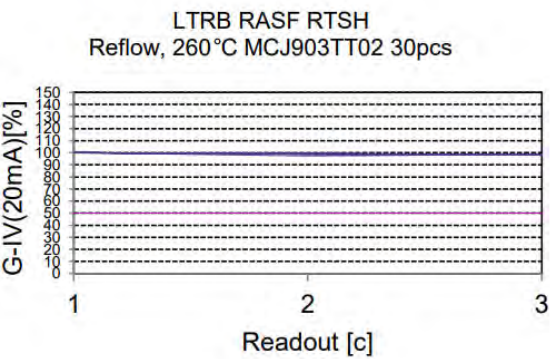
Blue chip



Red chip



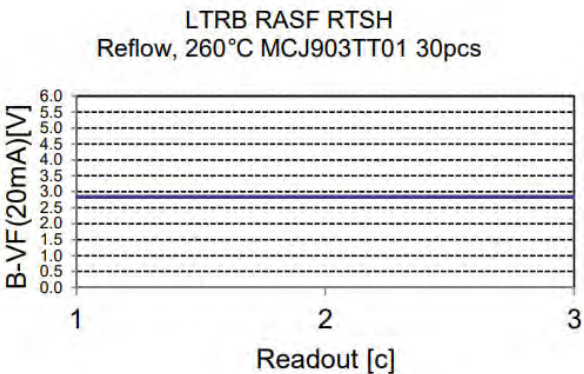
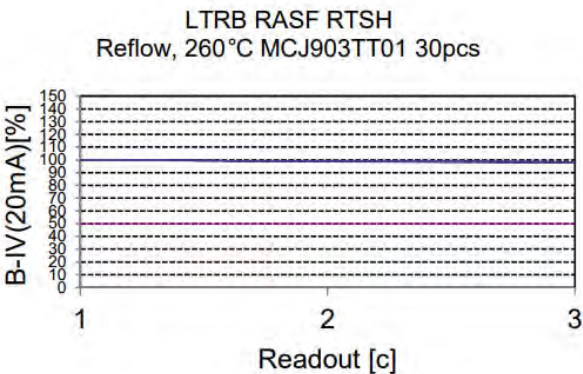
True green chip



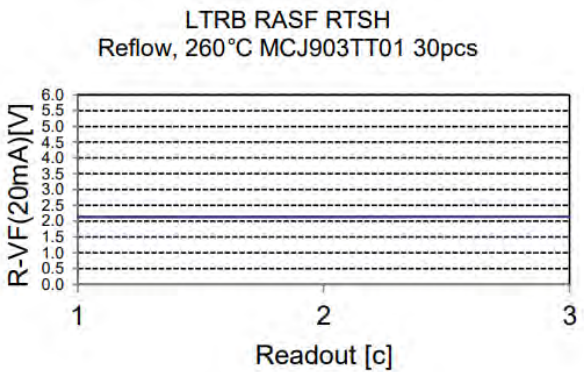
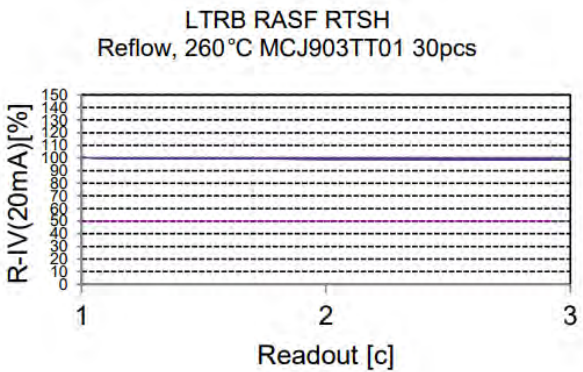
RSH Resistance to Solder Heat

Lot B - Eval

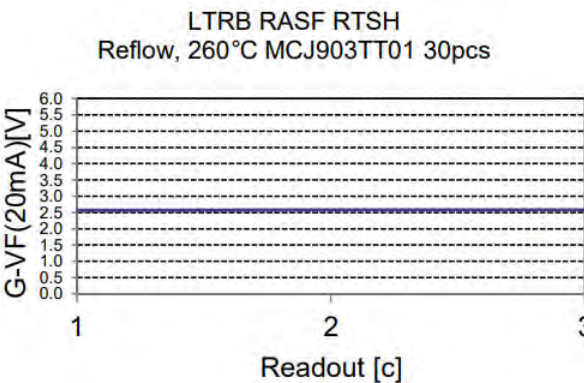
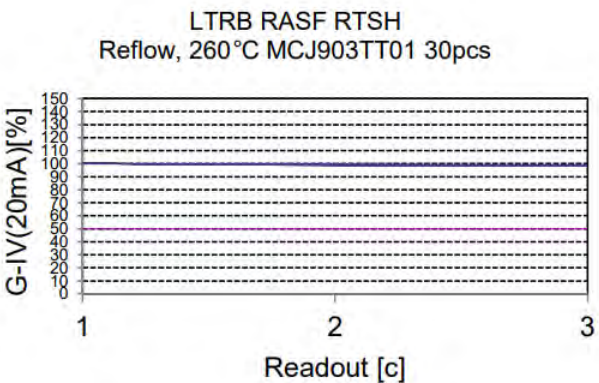
Blue chip



Red chip



True green chip

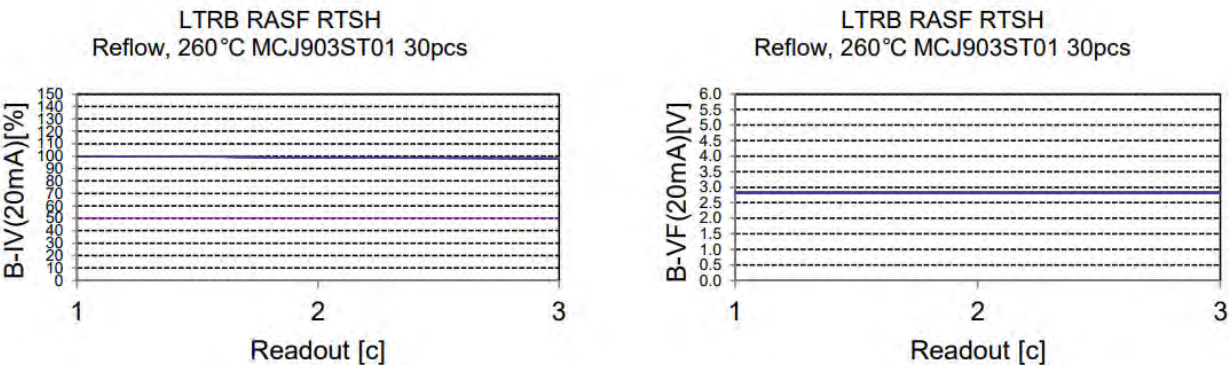




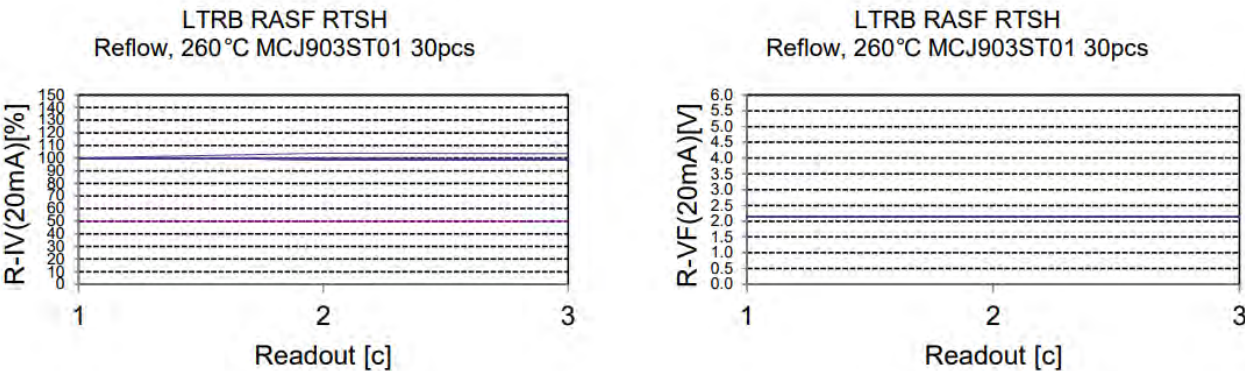
RSH Resistance to Solder Heat

Lot C - Eval

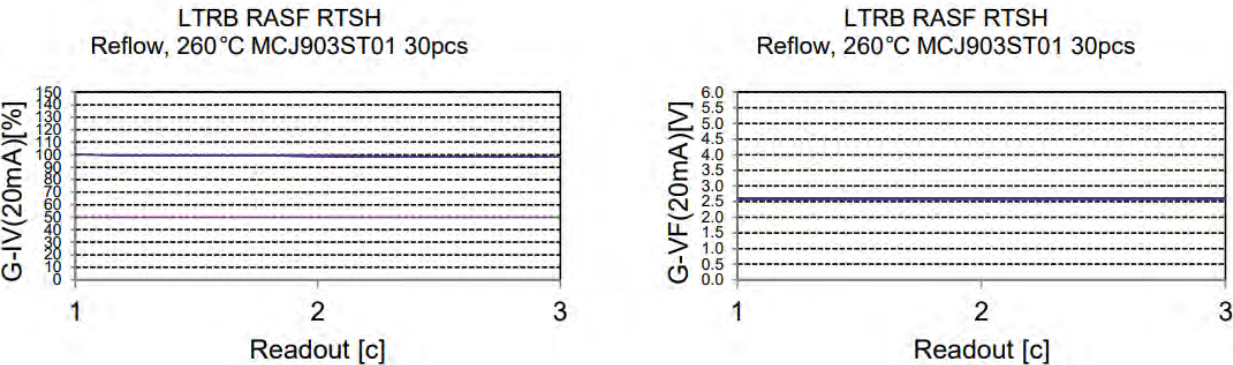
Blue chip



Red chip



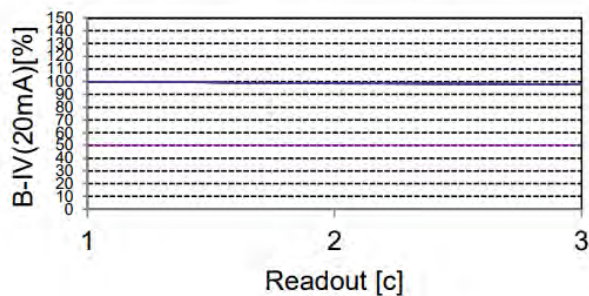
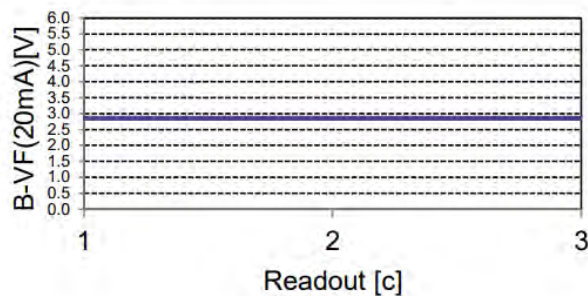
True green chip



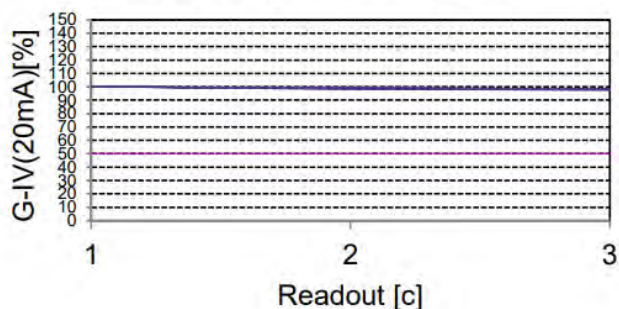
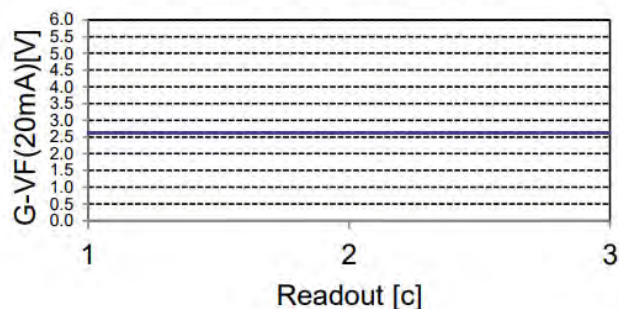
## RSH Resistance to Solder Heat

## Lot D - Control

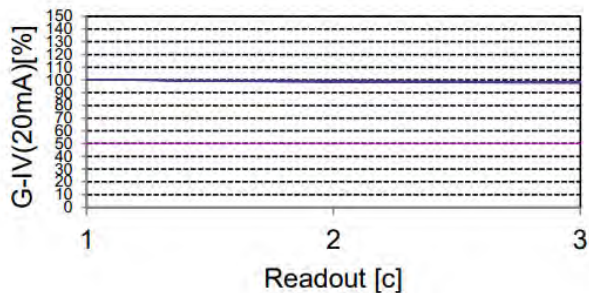
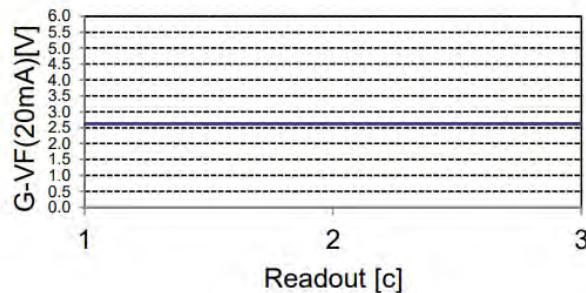
## Blue chip

LTRB RASF RTSH  
Reflow, 260°C 07P6H30314 30pcsLTRB RASF RTSH  
Reflow, 260°C 07P6H30314 30pcs

## Red chip

LTRB RASF RTSH  
Reflow, 260°C 07P6H30314 30pcsLTRB RASF RTSH  
Reflow, 260°C 07P6H30314 30pcs

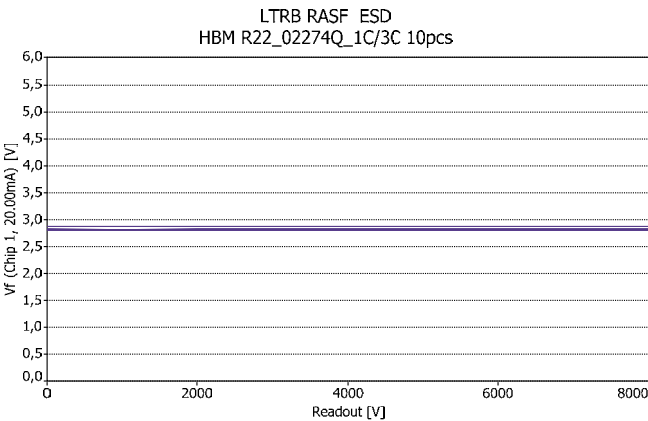
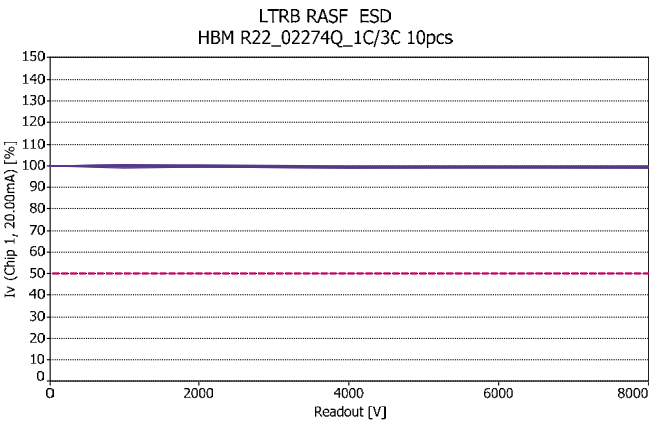
## True green chip

LTRB RASF RTSH  
Reflow, 260°C 07P6H30314 30pcsLTRB RASF RTSH  
Reflow, 260°C 07P6H30314 30pcs

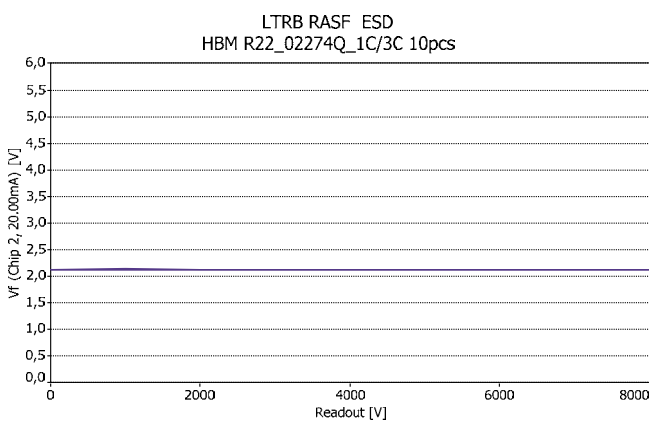
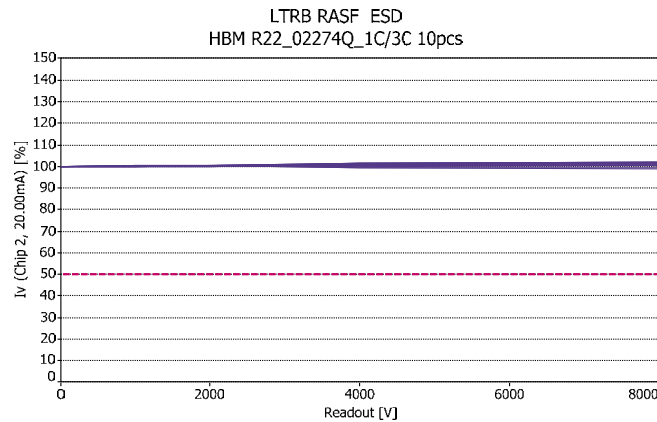
ESD HBM Human Body Model

Lot A - Eval

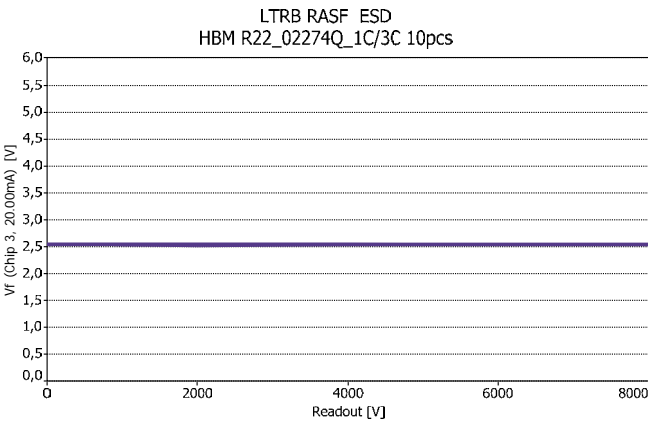
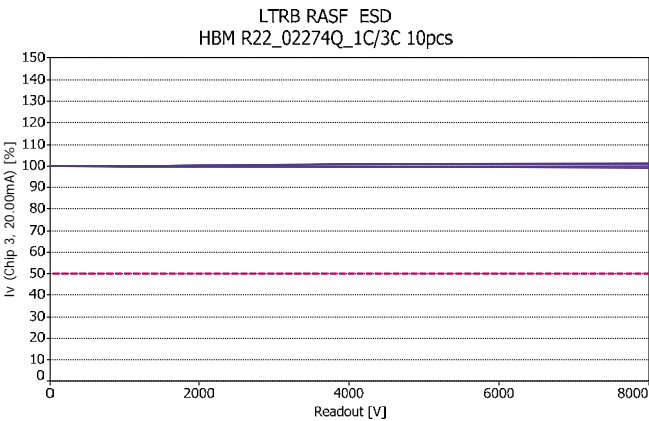
Blue chip



Red chip



True green chip

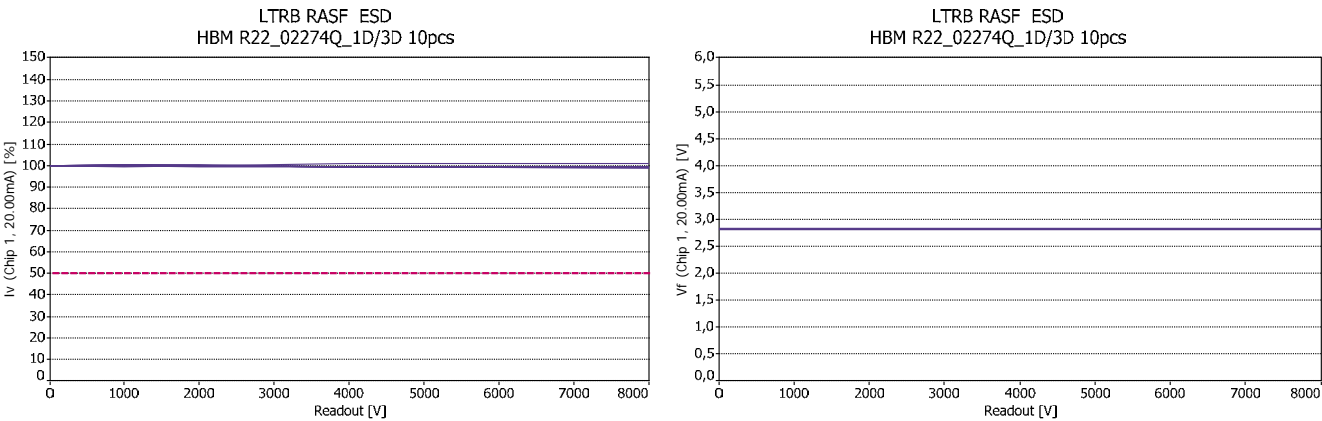




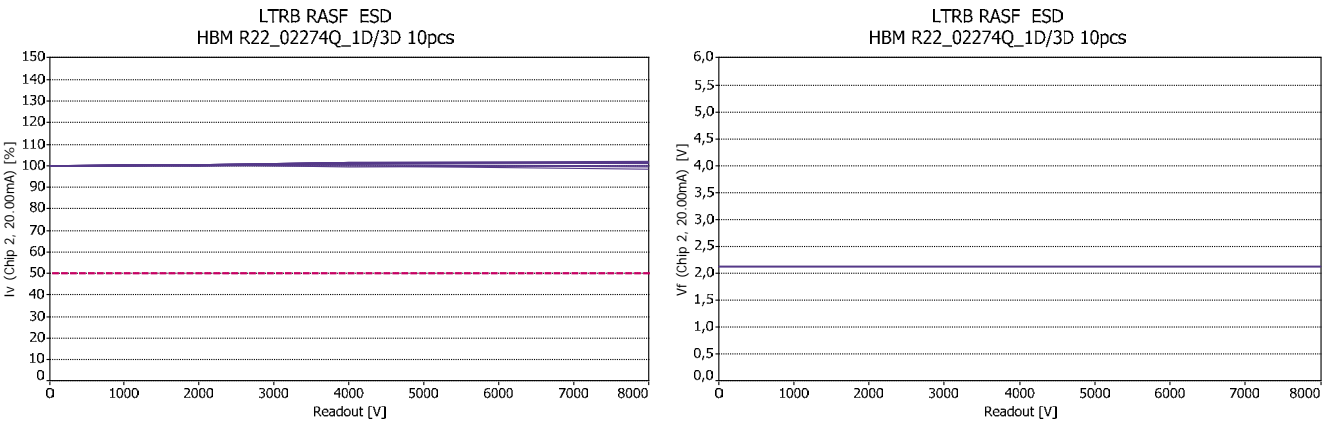
ESD HBM Human Body Model

Lot B - Eval

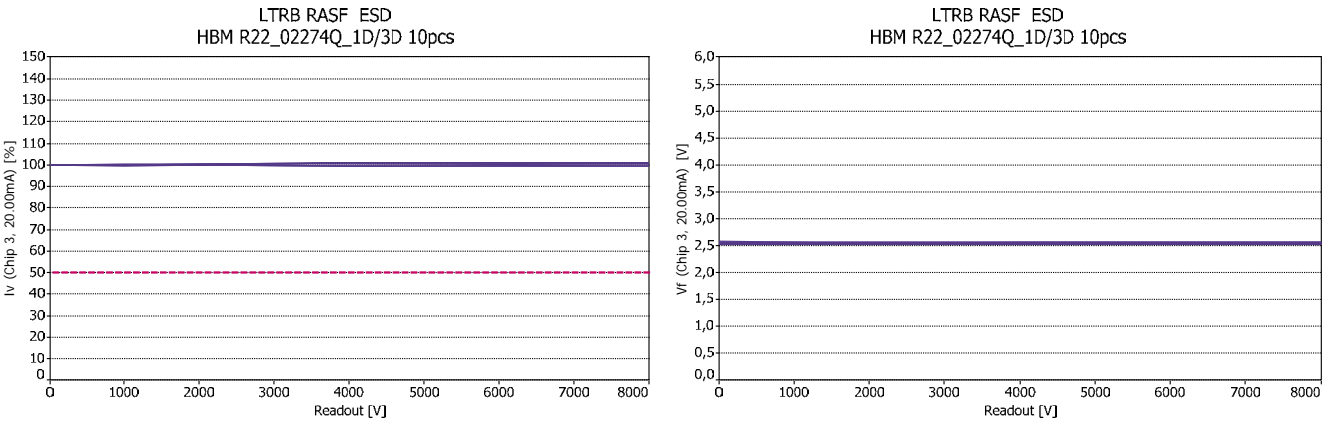
Blue chip



Red chip



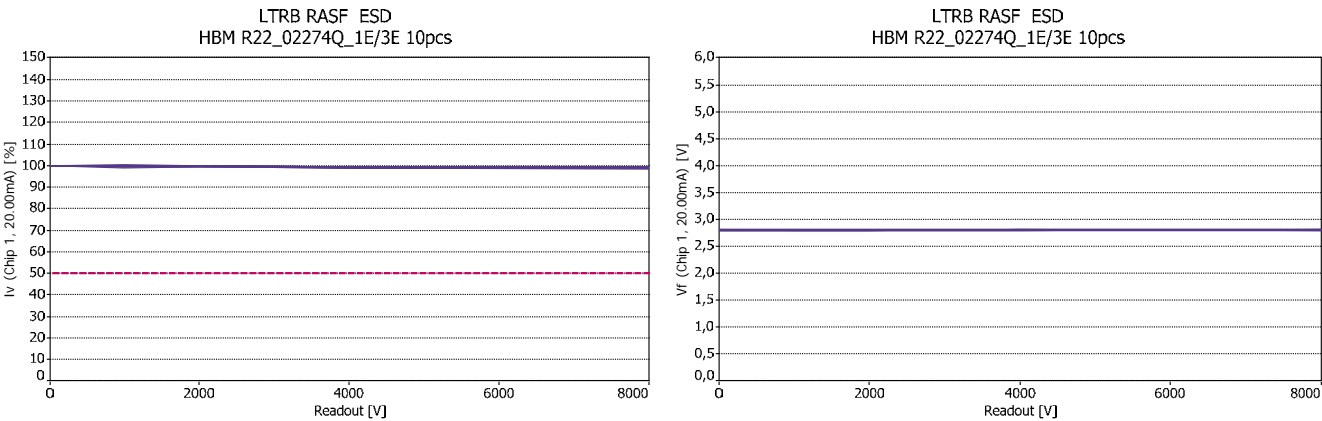
True green chip



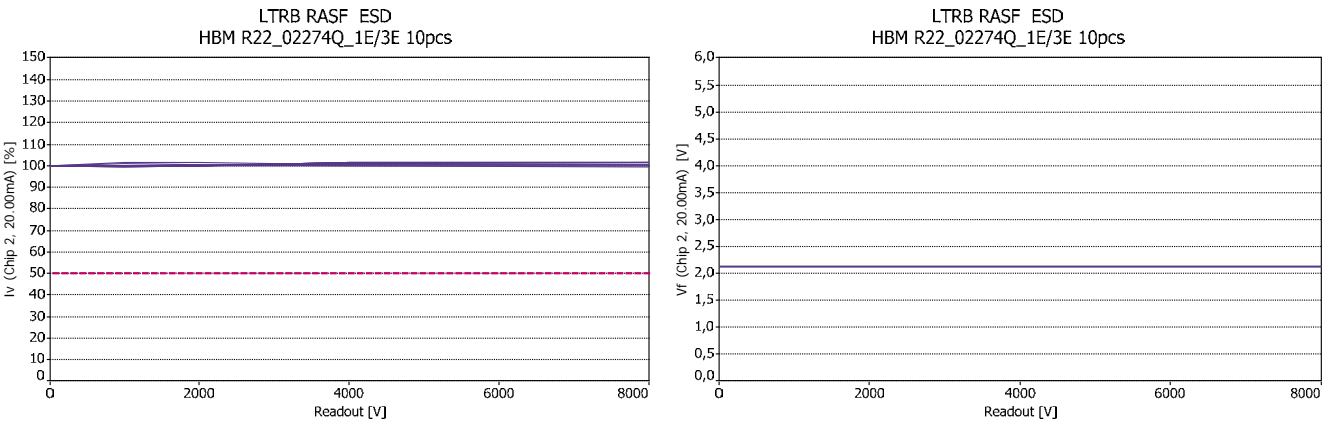
ESD HBM Human Body Model

Lot C - Eval

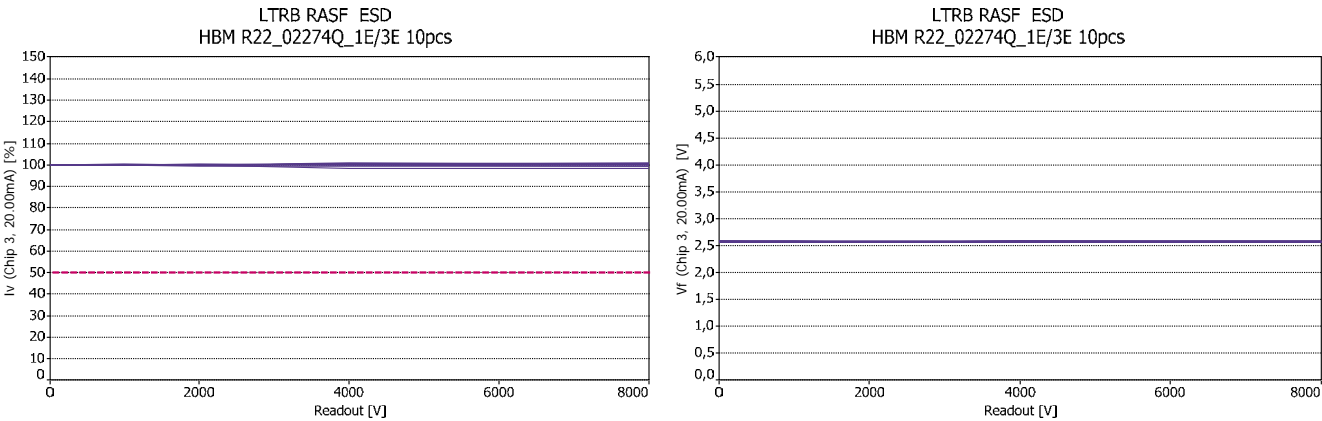
Blue chip



Red chip



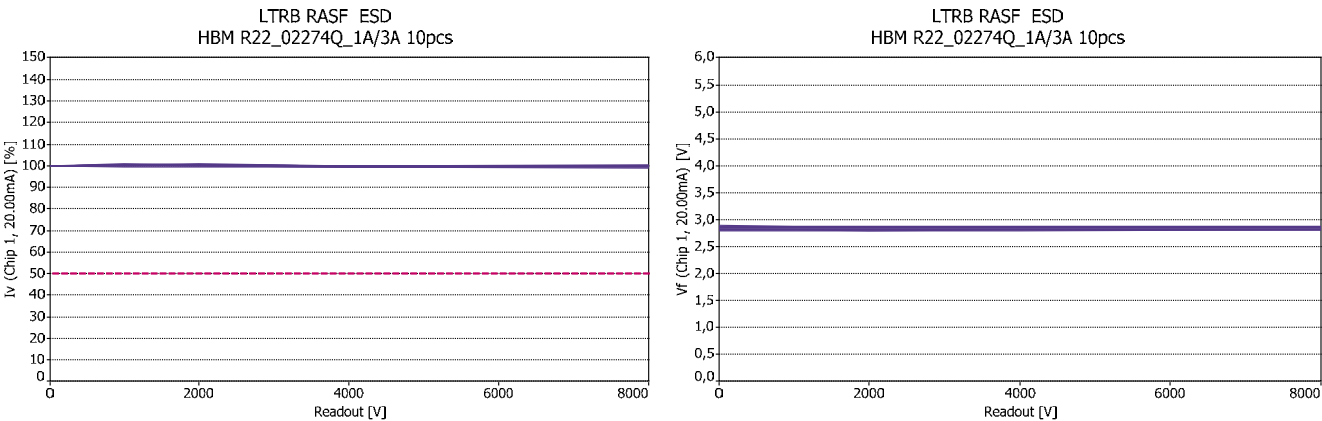
True green chip



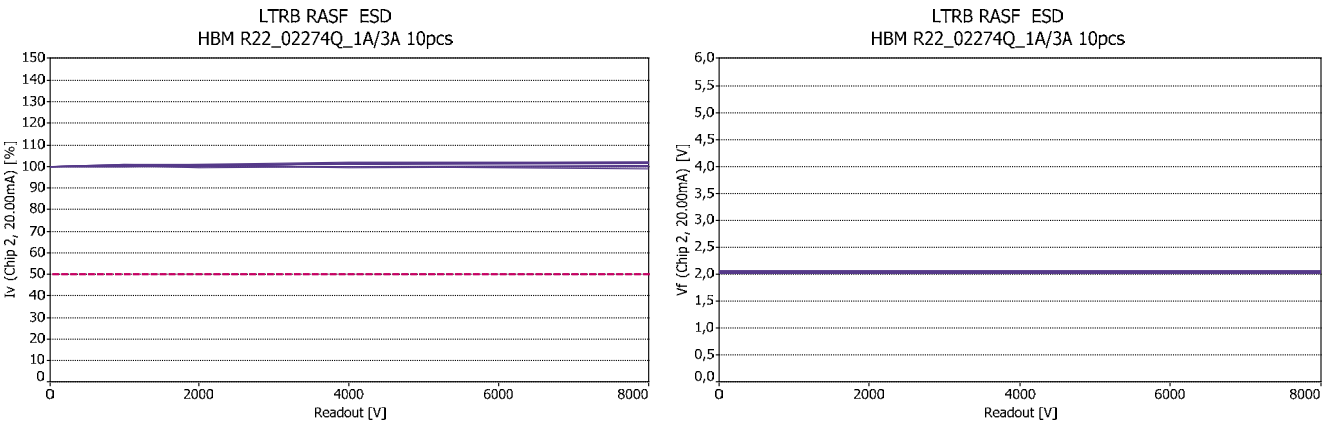
ESD HBM Human Body Model

Lot D - Control

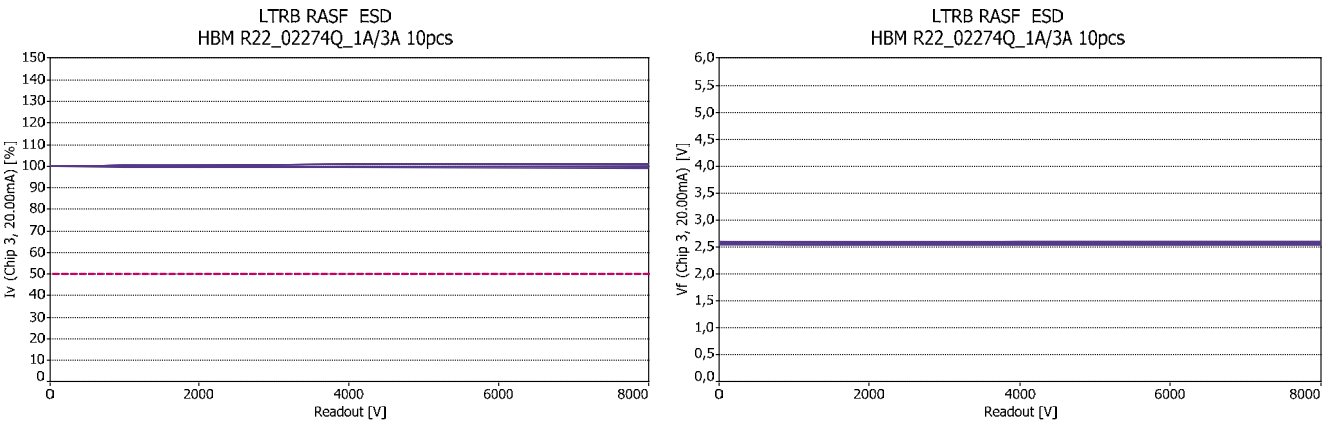
Blue chip



Red chip



True green chip





END OF DOCUMENT